

MILITARY SPECIFICATION

MICROCIRCUITS, LINEAR, MONOLITHIC AND HYBRID SILICON, MICROPROCESSOR COMPATIBLE, 12 BIT ANALOG-TO-DIGITAL CONVERTERS

This specification is approved for use by all Departments and Agencies of the Department of Defense.

1. SCOPE

1.1 Scope. This specification covers the detail requirements for monolithic and hybrid, microprocessor compatible, 12-bit successive approximation analog-to-digital converters buffered outputs. Two product assurance classes and a choice of case outlines and lead finishes are provided and are reflected in the complete part number.

1.2 Part number. The part number shall be in accordance with MIL-M-38510.

1.2.1 Device types. The device types shall be as follows:

Device type	Input voltage range (all device types) (pin programmable)	Technology	Performance grade
01	0 V to +10 V unipolar 0 V to +20 V unipolar -5 V to +5 V bipolar -10 V to +10 V bipolar	Monolithic	High
02	Same as defined for device type 01.	Monolithic	Medium
03	"	Hybrid	High
04	"	Hybrid	Medium
05	"	Monolithic	High
06	"	Monolithic	Medium

1.2.2 Device class. The device class shall be the product assurance level as defined in MIL-M-38510.

1.2.3 Case outline. The case outline shall be designated as follows:

Outline letter	Case outline, (see MIL-M-38510, appendix C)
X	D-10 (28-lead, 1/2" x 1-3/8"), dual-in-line package

Beneficial comments (recommendations, additions, deletions) and any pertinent data which may be of use in improving this document should be addressed to: Rome Air Development Center, (RBE-2), Griffiss AFB, NY 13441, by using the self-addressed Standardization Document Improvement Proposal (DD Form 1426) appearing at the end of this document or by letter.

1.3 Absolute maximum ratings.

Positive supply voltage (V_{CC}) to digital return - - - -	+18 V
Negative supply voltage (V_{EE}) to digital return - - - -	-18 V
Positive supply voltage (V_{LOG}) to digital return - - - -	+7 V
Digital input voltage to digital return - - - -	-0.5 V to V_{LOG}
	+0.5 V
Digital output voltage to digital return (Hi-Z output) - -	0 V to V_{LOG}
	+0.5 V
Analog return to digital return - - - -	+1 V
Analog input voltage to analog return - - - -	+16.5 V
±20 V analog input voltage to analog return - - - -	+24 V
V_{REF} out short to analog return - - - -	Indefinite
V_{REF} out short to V_{CC} - - - -	10 ms
Power dissipation - - - -	1000 mW
Lead temperature (soldering, 10 seconds) - - - -	300°C
Storage temperature - - - -	-65°C to +150°C
Junction temperature (may be exceeded during burn-in) - -	+175°C

1.4 Recommended operating conditions.

Positive supply voltage range (V_{CC}) - - - -	+11.4 to +16.5 V
Negative supply voltage range (V_{EE}) - - - -	-16.5 to -11.4 V
Positive supply voltage range (V_{LOG}) - - - -	+4.5 to 5.5 V
Ambient operating temperature range - - - -	-55°C to +125°C

1.5 Power and thermal characteristics.

Package	Case outline	Maximum allowable power dissipation	Maximum θ_{JC}	Maximum θ_{JA}
28 lead dual-in-line	X	1000 mW at $T_A = +125^\circ\text{C}$	25°C/W	60°C/W

2. APPLICABLE DOCUMENTS**2.1 Government documents.**

2.1.1 Specification and standard. The following specification and standard, form a part of this specification to the extent specified herein. Unless otherwise specified, the issues of these documents shall be those listed in the issue of the Department of Defense Index of Specifications and Standards and supplement thereto, cited in the solicitation.

SPECIFICATION**MILITARY**

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD**MILITARY**

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by contractors in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this specification and the references cited herein (except for associated detail specifications, specification sheets or MS standards), the text of this specification shall take precedence. Nothing in this specification, however, shall supersede applicable laws and regulations unless a specific exemption has been obtained.

TABLE I. Electrical performance characteristics.

Parameter <u>1/</u>	Symbol	Conditions (see 3.4 and figures 6 and 10 unless otherwise specified)	Limits		Units
			Min	Max	
Power supply current from V _{CC}	I _{CC}	Output code = 0000 0000 0000 and 1111 1111 1111 <u>2/</u>	1	16	mA
Power supply current from V _{EE}	I _{EE}	Output code = 0000 0000 0000 and 1111 1111 1111 <u>2/</u>	-30	-1	"
Power supply current from V _{LOG}	I _{LOG}	Output code = 0000 0000 0000 and 1111 1111 1111 <u>2/</u>	1	40	"
Power dissipation	P _d	(calculated worse case of 2 conditions) <u>3/</u>		725	mW
Input low current	I _{IL}	V _{LOG} = 5.5 V V _{IN} (LOGIC) = 0.0 V	-10	1	μA
Input high current	I _{IH}	V _{LOG} = 5.5 V V _{IN} (LOGIC) = 2.4 V	-1	10	"
		V _{IN} (LOGIC) = 5.5 V	-1	10	"
High impedance state output current	I _{ZL}	V _{LOG} = 5.5 V V _{IN} = 10.08 V min. Output code = 1111 1111 1111 <u>2/</u> Set R/C = Logic "0" Output bits 1 through 12 measured separately V _O = 0.0 V	-10	10	"
	I _{ZH}	V _{LOG} = 5.5 V V _{IN} = -7 mV max Output code = 0000 0000 0000 <u>2/</u> Set R/C = logic "0" Output bits 1 through 12 measured separately V _O = 5.5 V	-10	10	"
Conversion time	t _c	V _{IN} = -7 mV max Output code = 0000 0000 0000 <u>2/</u> 8-bit cycle			
		Device types 01, 02, 03, 04	10	29	μs
		Device types 05, 06	6	11.5	"
		12-bit cycle			
		Device types 01, 02, 03, 04	15	40	"
		Device types 05, 06	9	17	"

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.

Parameter 1/	Symbol	Conditions (see 3.4 and figures 6 and 10 unless otherwise specified)	Limits		Units
			Min	Max	
Output logic voltage levels	V _{OL}	V _{LOG} = 4.5 V Output code = 0000 0000 0000 <u>2/</u> Measure output bits 1-12 & STS I _L = 1.6 mA		0.4	V
	V _{OH}	V _{LOG} = 4.5 V Output code = 1111 1111 1111 <u>2/</u> Measure output bits 1-12 & STS I _L = -0.5 mA (Figures 6, 7, and 10)	2.4		"
Reference voltage	V _{REF}	Output code = 0000 0000 0000 <u>2/</u> Bipolar, VFSR = 20 V I _L = 1.5 mA			
		Device types 01, 02 Device types 03, 04, 05, 06	9.95 9.90	10.05 10.10	" "
Output operating modes (high byte)	m1	12/8 = 0.0 V A ₀ = logic "0" <u>5/</u> V _{IN} = 10.08 V min Output code = 1111 1111 XXXX I _L = -0.5 mA Measure output bits 1-8	2.4		"
(low byte)	m2	12/8 = 0.0 V A ₀ = logic "1" <u>5/</u> V _{IN} = 10.08 V min Output code = XXXX 0000 1111 I _L = -0.5 mA Measure output bits 9-12	2.4		"
(middle nybble override, trailing zeros)	m3	12/8 = 0.0 V A ₀ = logic "1" <u>5/</u> V _{IN} = 10.08 V min Output code = XXXX 0000 1111 I _L = -1.6 mA Measure output bits 5-8		0.4	"
(high nybble Hi-Z)	m4	12/8 = 0.0 V A ₀ = logic "1" <u>5/</u> V _{IN} = 10.08 V min Output code = XXXX 0000 1111 V _O = 0.4 V Measure output bits 1-4	-10	10	μA
(low nybble Hi-Z)	m5	12/8 = 0.0 V A ₀ = logic "0" <u>5/</u> V _{IN} = 10.08 V min Output code = 1111 1111 XXXX V _O = 0.4 V Measure output bits 9-12	-10	10	μA

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.

Parameter 1/	Symbol	Conditions (see 3.4 and figures 6 and 10 unless otherwise specified)	Limits		Units
			Min	Max	
Logic thresholds	$V_{R/\overline{C}}$	$V_{IN} = -7$ mV max $V_{R/C} = 0.8$ V (initial) $V_{R/\overline{C}} = 2.0$ V Output code = 0000 0000 0000			(Logic "0")
		$V_{IN} = 10.08$ V min $V_{R/C} = 0.8$ V (initial) $V_{R/\overline{C}} = 2.0$ V Output code = 1111 1111 1111			(Logic "1")
	V_{CE}	$V_{IN} = 10.08$ V min $V_{CE} = 2.0$ V, convert Output code = 1111 1111 1111			(Logic "1")
		$V_{IN} = -7$ mV max $V_{CE} = 0.8$ V Output code = 1111 1111 1111			(Logic "1")
		$V_{IN} = -7$ mV max $V_{CE} = 2.0$ V, convert Output code = 0000 0000 0000			(Logic "0")
	V_{CS}	$V_{IN} = 10.08$ V min $V_{CE} = \text{logic "1"}$ $V_{CS} = 0.8$ V, convert Output code = 1111 1111 1111			(Logic "1")
		$V_{CS} = 2.0$ V $V_{CE} = \text{logic "1"}$ $V_{IN} = -7$ mV max Output code = 1111 1111 1111			(Logic "1")
		$V_{IN} = -7$ mV max $V_{CE} = \text{logic "1"}$ $V_{CS} = 0.8$ V, convert Output code = 0000 0000 0000			(Logic "0")
	V_{AO}	$V_{IN} = 10.08$ V min $I_{2/8} = 0.0$ V $V_{AO} = 0.8$ V, convert Output code = 1111 1111 XXXX Measure output bits 5-8			(Logic "1")
		$V_{CE} = \text{logic "0"}$ $V_{AO} = 2.0$ V, $V_{CE} = \text{logic "1"}$ Output code = XXXX 0000 1111 Measure outputs bits 5-8			(Logic "0")

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.

Parameter 1/	Symbol	Conditions (see 3.4 and figures 6 and 10 unless otherwise specified)	Limits		Units
			Min	Max	
Power supply sensitivity to V_{CC}	+PSS1	13.5 V $\leq V_{CC} \leq$ 15.0 V, 15.0 V $\leq V_{CC} \leq$ 16.5 V Output transition = 0000 0000 0000 and 1111 1111 1111 <u>6/</u>	-.10	.10	LSB/ %PS
	+PSS2	11.4 V $\leq V_{CC} \leq$ 12.0 V, 12.0 V $\leq V_{CC} \leq$ 12.6 V Output transition = 0000 0000 0000 and 1111 1111 1111 <u>6/</u> (Figures 8 and 10)	-.20	.20	"
Power supply sensitivity to V_{LOG}	+PSS3	4.5 V $\leq V_{LOG} \leq$ 5.0 V, 5.0 V $\leq V_{LOG} \leq$ 5.5 V Output transition = 0000 0000 0000 and 1111 1111 1111 <u>6/</u> (Figures 8 and 10)	-.10	.10	"
Power supply sensitivity to V_{EE}	-PSS1	-16.5 V $\leq V_{EE} \leq$ -15.0 V, -15.0 V $\leq V_{EE} \leq$ -13.5 V Output transition = 0000 0000 0000 and 1111 1111 1111 <u>6/</u>	-.10	.10	"
	-PSS2	-12.6 V $\leq V_{EE} \leq$ -12.0 V, -12.0 V $\leq V_{EE} \leq$ -11.5 V Output transition = 0000 0000 0000 and 1111 1111 1111 <u>6/</u> (Figures 8 and 10)	-.20	.20	"
Missing code check	MCC	All codes check	0	0	Codes
Unipolar offset voltage	V_{IO}	Output transition = 0000 0000 0000 <u>6/</u> $T_A = 25^\circ\text{C}$ Device types 01, 02 Initial End point	-0.5 -1.0	1.5 2.0	LSB "
		Device types 03, 04, 05, 06 Initial End point	-1.5 -2.0	2.5 3.0	" "
		(Figures 8 and 10)			
Unipolar offset voltage drift	dy_{IO}/dT	Output transition = 0000 0000 0000 <u>6/</u> Device types 01, 02 Device types 03, 04, 05, 06 (Figures 8 and 10)	-0.5 -1.0	0.5 1.0	" "

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.

Parameter 1/	Symbol	Conditions (see 3.4 and figures 6 and 10 unless otherwise specified)	Limits		Units
			Min	Max	
Bipolar zero	BZ	Output code = 0000 0000 0000 6/ Bipolar, VFSR = 20 V Initial End point T _A = 25°C (Figures 8 and 10)	-4.5 -5.5	3.5 4.5	LSB "
Bipolar zero drift	dBZ /dT	Output code = 0000 0000 0000 6/ Bipolar, VFSR = 20 V Device types 01, 03, 05 Device types 02, 04, 06 (Figures 8 and 10)	-1 -2	1 2	" "
Gain error	AE	Output transition = 0000 0000 0000 and 1111 1111 1110 6/			
		Device type 01 Initial End point	-0.125 -0.225	0.125 0.225	%FSR "
		Device type 02 Initial End point	-0.25 -0.35	0.25 0.35	" "
		Device types 03, 04, 05, 06 Initial End point	-0.3 -0.4	0.3 0.4	" "
Gain error drift	BpAE	Bipolar, VFSR = 20 V T _A = 25°C			
		Device type 01	-0.125	0.125	"
		Device type 02	-0.25	0.25	"
		Device types 03, 04, 05, 06 (Figures 8 and 10)	-0.3	0.3	"
Gain error drift	dAE /dT	Output transition = 0000 0000 0000 and 1111 1111 1110			
		Device types 01, 03, 05	-12.5	12.5	ppm
		Device types 02, 04, 06	-25	25	/°C
		Bipolar, VFSR = 20 V Device types 01, 03, 05 Device types 02, 04, 06 (Figures 8 and 10)	-12.5 -25	12.5 25	" "
Integral linearity error	LE	(Abbreviated test) -55°C ≤ T _A ≤ 125°C T _A = 25°C (Figures 8 and 10)	-1.0 -0.5	1.0 0.5	LSB "
Integral linearity error	LE	(All codes test) -55°C ≤ T _A ≤ 125°C T _A = 25°C (Figures 8 and 10)	-1.0 -0.5	1.0 0.5	" "

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.

Parameter <u>1/</u>	Symbol	Conditions (see 3.4 and figures 6 and 10 unless otherwise specified)	Limits		Units
			Min	Max	
Differential linearity error	D _{LE}	(Abbreviated test) -55°C < T _A ≤ 125°C T _A = 25°C (Figures 8 and 10)	-0.9 -0.9	2.0 1.0	" "
STS delay from CE	t _{DSC}	Low to high transition, referenced to low to high CE transition Output code = 0000 0000 0000 <u>2/</u> T _A = 25°C (Figures 9 and 10)		350	ns
Data access time from CE	t _{DD}	Output data valid, referenced to low to high CE transition Output code = 0000 0000 0000 and 1111 1111 1111 <u>2/</u> T _A = 25°C Device types 01, 02, 03, 04 Device types 05, 06 (Figures 9 and 10)		200 250	ns "
Data valid after CE low	t _{HD}	Output data valid, referenced to high to low CE transition Output code = 0000 0000 0000 and 1111 1111 1111 <u>2/</u> T _A = 25°C (Figures 9 and 10)	25		"
STS delay after data valid	t _{HS}	High to low transition referenced to data valid Output code = 0000 0000 0000 and 1111 1111 1111 <u>2/</u> T _A = 25°C Device types 01, 02, 03, 04 Device types 05, 06 (Figures 9 and 11)	300 100	1000 600	" "
Output float delay	t _{HL}	Output delay to Hi-Z, referenced to high to low CE transition Output code = 0000 0000 0000 and 1111 1111 1111 <u>2/</u> T _A = 25°C Device types 01, 02 Device types 03, 04, 05, 06 (Figures 9 and 10)		100 150	" "
STS delay from R/C	t _{DS}	Low to high transition, referenced to high to low R/C transition Output code = 0000 0000 0000 <u>2/</u> T _A = 25°C (Figures 9 and 11)		600	"

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.

Parameter ^{1/}	Symbol	Conditions (see 3.4 and figures 6 and 10 unless otherwise specified)	Limits		Units
			Min	Max	
Data access time from R/C	t _{DDR}	Output data valid, referenced to low to high low R/C transition Output code = 0000 0000 0000 and 1111 1111 1111 ^{2/} T _A = 25°C (Figures 9 and 11)		250	"
Data valid after R/C low	t _{HDR}	Output data valid, referenced to high to low R/C transition Output code = 0000 0000 0000 and 1111 1111 1111 ^{2/} T _A = 25°C (Figures 9 and 11)	25		ns
Output short circuit current	I _{OSC}	V _{LOG} = 5.5 V Output code = 1111 1111 1111 and ^{2/} STS output = logic "1" measured separately to ground Output code = 0000 0000 0000 and ^{2/} STS output = logic "0" measured separately to V _{LOG} T _A = 25°C	-40	75	mA mA
Input resistance	R _i	V _{IN} (analog) = 1/2 V T _A = 25°C	3	7	kohms
Transition uncertainty	NT	Output transition = 0000 0000 0000 and 1111 1111 1111 ^{6/} Range = 16% to 94% T _A = 25°C (Figures 8 and 10)	-0.5	0.5	LSB

^{1/} See paragraph 6.5 for symbols and definitions.

^{2/} An output code of 0000 0000 0000 is guaranteed by an input voltage V_{IN} = -7.0 mV and an output code of 1111 1111 1111 is guaranteed by an input voltage V_{IN} = 10.08 V.

^{3/} P_d = (V_{CC} * I_{CC} + V_{EE} * I_{EE} + V_{LOGIC} * I_{LOGIC}). Power dissipation shall be calculated using the two output code conditions 0000 0000 0000 and 1111 1111 1111.

^{4/} The reference voltage external load current shall be constant dc and shall not exceed 1.5 mA.

^{5/} Changing A₀ during the ready cycle, may result in damage to the device output buffers. Therefore, it is recommended that CE is low or CS is high before A₀ is changed.

^{6/} 0 represents the transition point between two adjacent code-words (i.e: 0000 0000 0000) represents the transition between code-words 0000 0000 0000 and 0000 0000 0001, 0000 0000 0000 represents the transition between code-words 0111 1111 1111 and 1000 0000 0000 and 1111 1111 1110 represents the transition between code-words 1111 1111 1110 and 1111 1111 1111.

3. REQUIREMENTS

3.1 Detail specification. The individual item requirements shall be in accordance with MIL-M-38510, and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

3.2.1 Case outline. The case outline shall be as specified in 1.2.3 herein.

3.2.2 Functional diagram and terminal connections. The functional diagram and terminal connections shall be as specified on figures 1 and 2.

3.2.3 Functional block diagram. The functional block diagram shall be as specified on figure 4.

3.2.4 Schematic circuits. The schematic circuits shall be submitted to the preparing activity prior to inclusion of manufacturer's device in this specification and shall be submitted to the qualifying activity and agent activity (DESC-ECS) as a prerequisite for qualification. All qualified manufacturers' schematics shall be maintained by the agent activity and will be available upon request.

3.2.5 Package and sealing material. Package and sealing material shall be in accordance with MIL-M-38510 (see 6.5).

3.3 Lead material and finish. The lead material and finish shall be in accordance with MIL-M-38510 and 6.3 herein.

3.4 Electrical performance characteristics. The electrical performance characteristics are as specified in table I, and apply over the full recommended ambient operating temperature range, unless otherwise specified. The following conditions shall also apply unless otherwise specified:

Unipolar operation	VFSR = 10 V
V _{CC} = +15.0 V	VEE = -15.0 V
CS input = logic "0"	Logic "0" = 0.8 V maximum
CE input = logic "1"	Logic "1" = 2.0 V minimum
12/8 input = V	VLOG = +5.0 V
-55°C ≤ T _A ≤ +125°C	

3.5 Electrical test requirements. The electrical test requirements for each device class shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table III.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (see table III) 1/	
	Class S devices	Class B 2/ devices
Interim electrical parameters (method 5004)	1	1
Final electrical test parameters (method 5004)	1, 2, 3, 4, 5, 6	1, 2, 3, 4, 5, 6
Group A test requirements (method 5005)	1, 2, 3, 4, 5, 6, 7, 8, 9	1, 2, 3, 4, 5, 6, 7, 8, 9
Group C end-point electrical parameters (method 5005)	1, 4 and table IV delta limits	1, 4 and table IV delta limits
Additional electrical subgroups for group C periodic inspections	N/A	---
Group D end-point electrical parameters (method 5005)	1, 2, 3, 4, 5, 6	1, 4

1/ PDA applies to subgroup 1 (see 4.2c).

2/ Subgroup 8, as listed in table III, test 581 through test 588 is used for initial and redesign qualification (class B only).

3.6 Marking. Marking shall be in accordance with MIL-M-38510.

3.6.1 Serialization. All class S devices shall be serialized in accordance with MIL-M-38510.

3.6.2 Correctness of indexing and markings. All devices shall be subjected to the final electrical tests subgroups 1 and 4 specified in table II after part marking to verify that they are correctly indexed and identified by part number. Optionally, an approved electrical test may be devised especially for this requirement.

3.7 Microcircuit group assignment. The devices covered by this specification shall be in microcircuit technology group I and 57 (see MIL-M-38510, appendix E).

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-M-38510 methods 5005 and 5007, as applicable, of MIL-STD-883, except as modified herein.

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to qualification and quality conformance inspection. The following additional criteria shall apply:

- a. Burn-in tests (method 1015 of MIL-STD-883).
 - (1) Class S devices: Dynamic tests (test condition D) using the circuit shown on figure 5. Test duration shall be as defined in MIL-STD-883.
 - (2) Class B devices: Test condition D, using the circuit shown on figure 5.
- b. Interim and final electrical test parameters shall be as specified in table II, except interim electrical parameters tests prior to burn-in is optional at the discretion of the manufacturer.
- c. The percent defective allowable (PDA) for class S and class B devices shall be as specified in MIL-M-38510, based on failures from group A, subgroup 1 test after cooldown as final electrical tests in accordance with method 5004 of MIL-STD-883 and with no intervening electrical measurements. If interim electrical parameter tests are performed prior to burn-in, failures resulting from pre burn-in screening may be excluded from the PDA. If interim electrical parameter tests prior to burn-in are omitted, then all screening failures shall be included in the PDA. The verified failures of group A, subgroup 1 after burn-in divided by the total number of devices submitted for burn-in in that lot shall be used to determine the percent defective for that lot, and the lot shall be accepted or rejected based on the PDA for the applicable device class.
- d. Internal visual inspection (methods 2010 and 2017 (multi-chip criteria) of MIL-STD-883). For multichip devices, internal visual inspection shall be performed for each chip within the package.

4.3 Qualification inspection. Qualification inspection shall be in accordance with MIL-M-38510. Inspections to be performed shall be specified in method 5005 of MIL-STD-883, and herein for groups A, B, C, and D inspections (see 4.4.1 through 4.4.4).

4.3.1 Qualification extension. For qualification inspection, if a manufacturer qualifies to device type 01 (monolithic) or device type 03 (hybrid), which is designed and manufactured identically (same die or dice, same process, same screening) in all respects (except electrical testing) to device type 02 (monolithic) or device type 04 (hybrid) respectively, then qualification may be extended to device type 02 or 04 respectively when authorized by the qualifying activity. Additionally, part I qualification may be extended to device type 02 or 04 respectively only after acceptance by the qualifying activity of subgroup C1 testing performed on the AT device type (see 6.6) and submission of data in accordance with MIL-M-38510, appendix D.

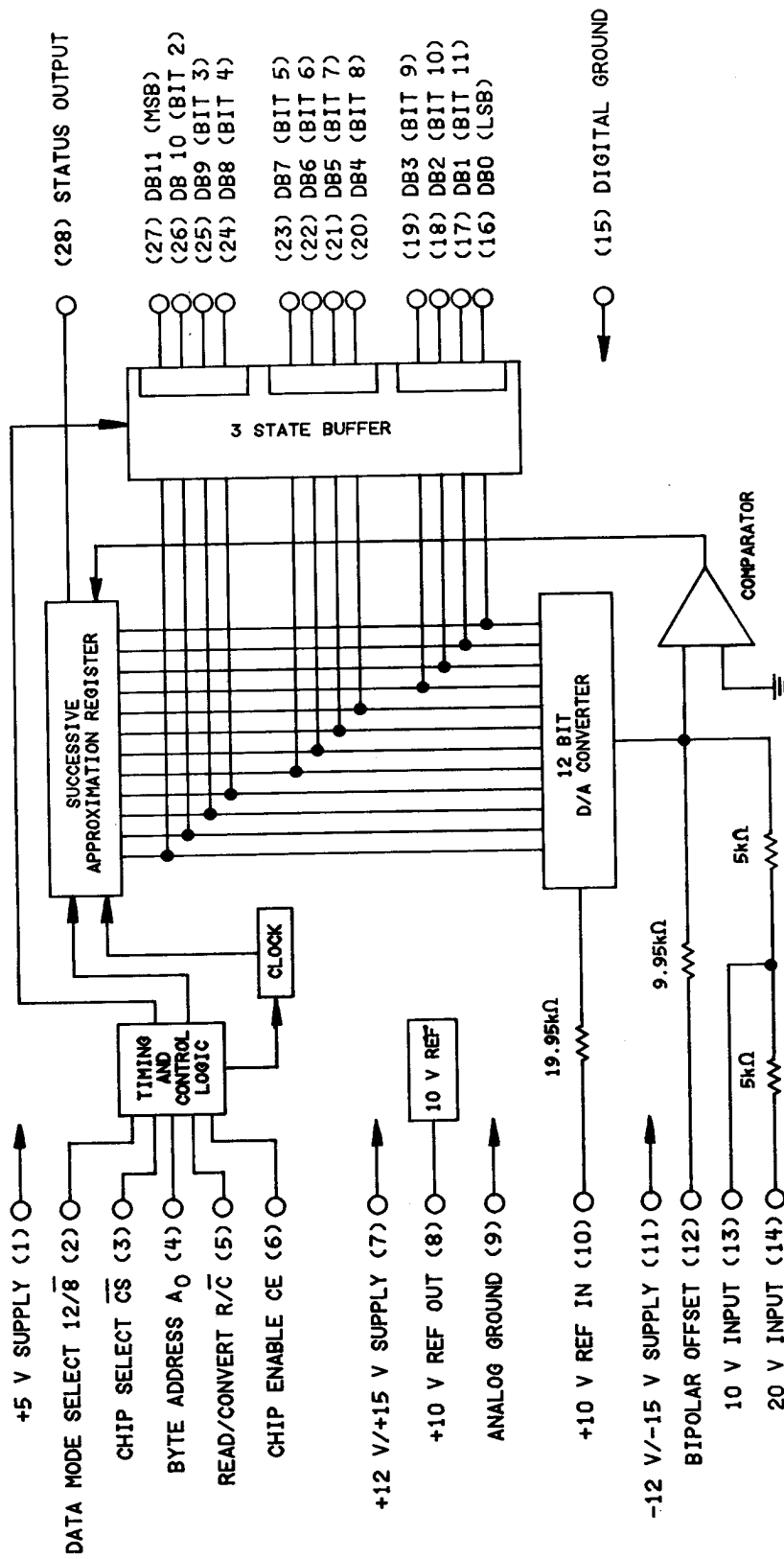


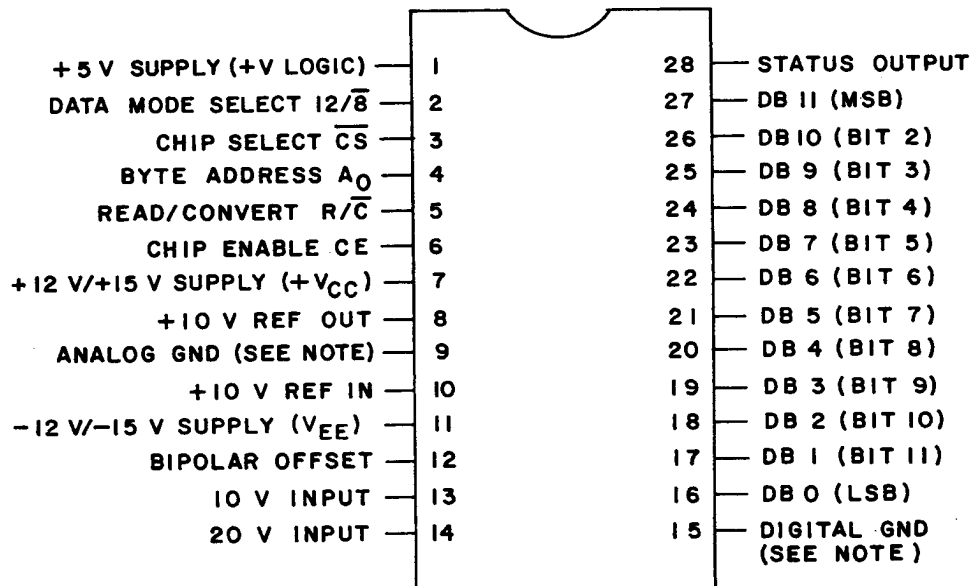
FIGURE 1. Functional block diagram and operational information.

ANALOG INPUT VOLTAGE (VOLTS)				DIGITAL OUTPUT	
0 to +10 V	0 to +20V	±5V	±10V	MSB	LSB
+10.0000 + 9.9963	+20.0000 +19.9927	+5.0000 +4.9963	+10.0000 + 9.9927	1111 1111 1111 1111 1111 1110	
+ 5.0012 + 4.9988 + 4.9963	+10.0024 + 9.9976 + 9.9927	+0.0012 -0.0012 -0.0037	+ 0.0024 - 0.0024 - 0.0073	1000 0000 0000 0000 0000 0000 0111 1111 1110	
+ 0.0012 + 0.0000	+ 0.0024 0.0000	-4.9988 -5.0000	- 9.9976 -10.0000	0000 0000 0000 0000 0000 0000	

Control Inputs					Operation
CE	$\overline{CS}$	$\overline{R/\overline{C}}$	$12/\overline{8}$	A_0	
0	X	X	X	X	No operation
X	1	X	X	X	No operation
1	0	1-0	X	0	Initiates 12-bit conversion
1	0	1-0	X	1	Initiates 8-bit conversion
0-1	0	0	X	0	Initiates 12-bit conversion
0-1	0	0	X	1	Initiates 8-bit conversion
1	1-0	0	X	0	Initiates 12-bit conversion
1	1-0	0	X	1	Initiates 8-bit conversion
1	0	0-1	V_{LOG}	X	Enables 12-bit parallel output
1	0	0-1	0.0V	0	Enables 8 MSB's
1	0	0-1	0.0V	1	Enables 4 LSB's and 4 trailing zeros

FIGURE 1. Functional block diagram and operational information - Continued.

All device types
Cases X, Y and Z



NOTE: The units two ground pins (pins 9 and 15) must be connected together as close to the package as possible, and preferably should be connected to a large analog ground plane underneath the package. If these commons must be run separately, a non-polarized 0.01 μ F bypass capacitor should be connected between pins 9 and 15 as close to the unit as possible and wide conductor runs should be employed.

FIGURE 2. Terminal connections.

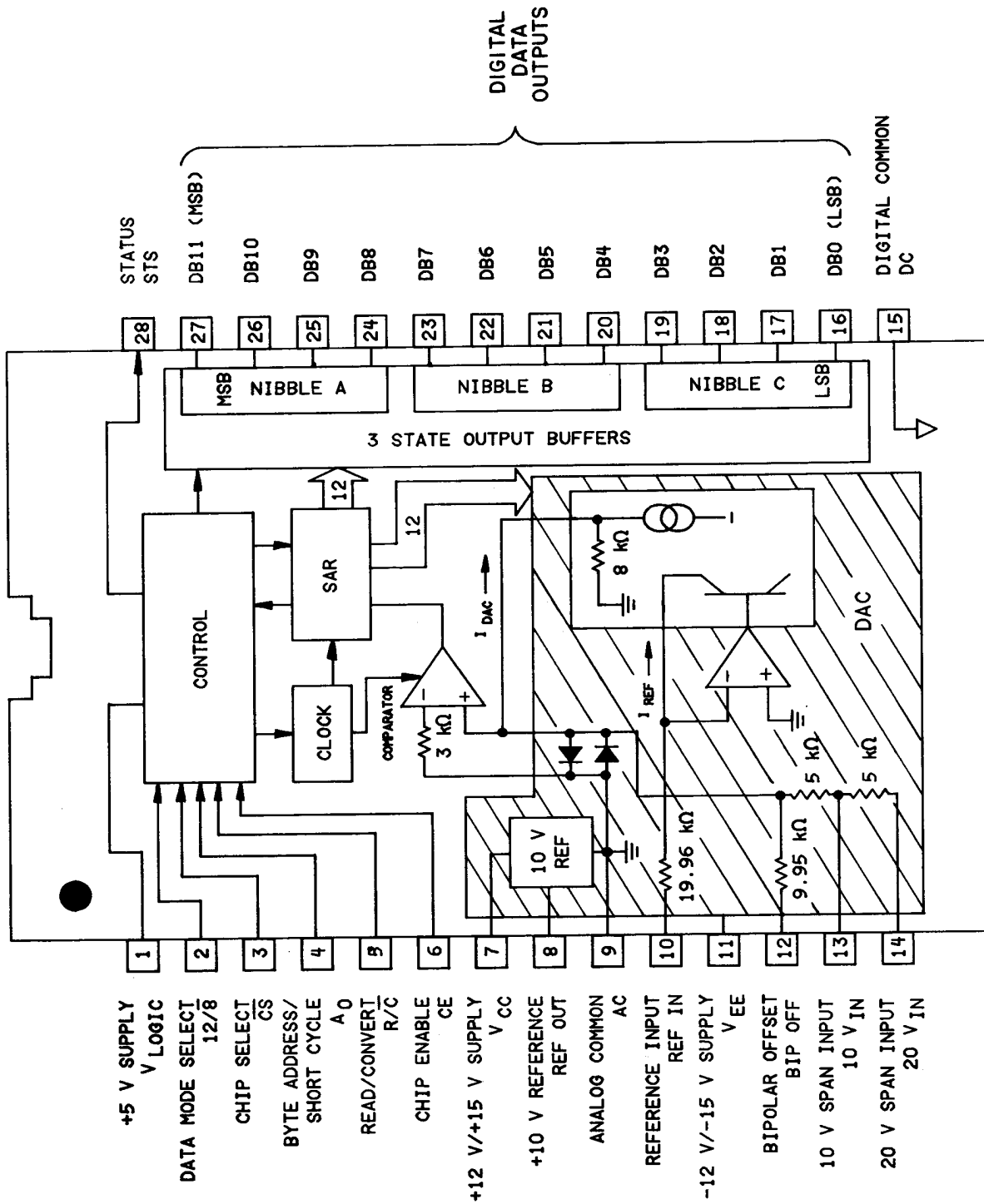
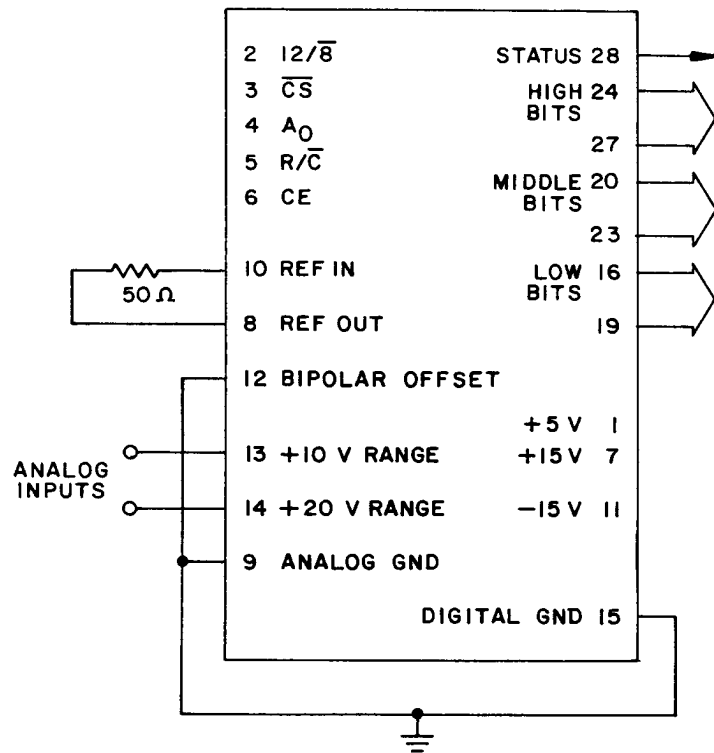


FIGURE 3. Functional block diagram.

UNIPOLAR OPERATION WITHOUT TRIM ADJUSTMENT



UNIPOLAR OPERATION WITH TRIM ADJUSTMENT

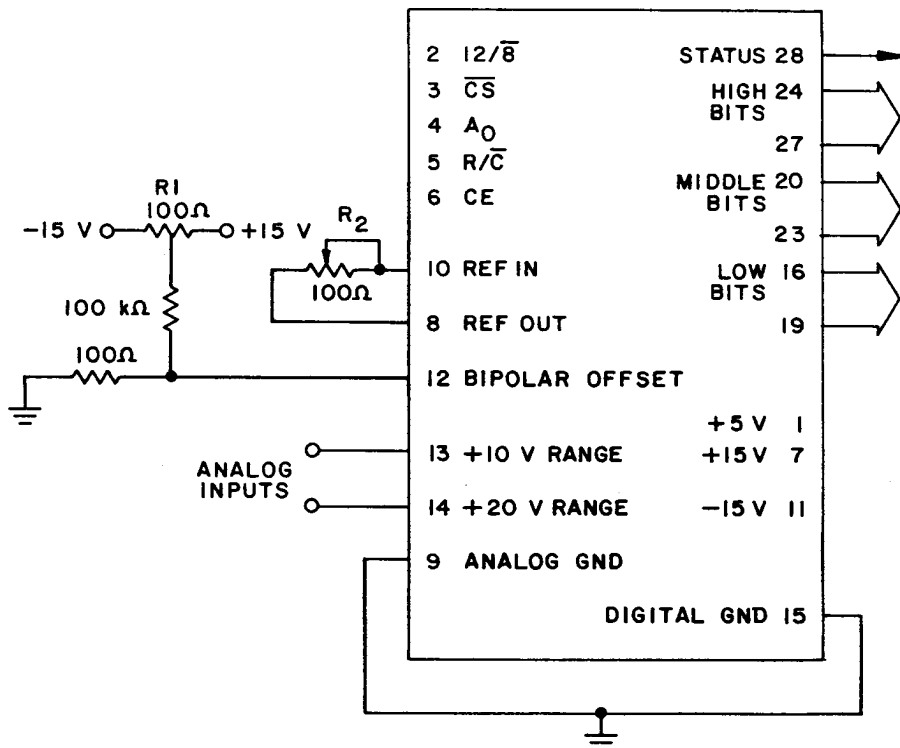
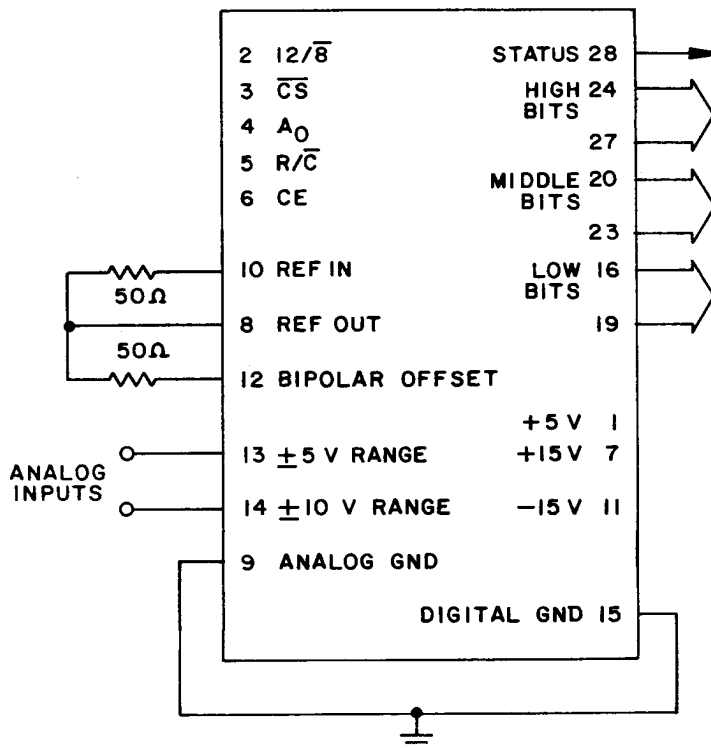


FIGURE 4. Functional schematics with application notes.

BIPOLAR OPERATION WITHOUT TRIM ADJUSTMENT



BIPOLAR OPERATION WITH TRIM ADJUSTMENT

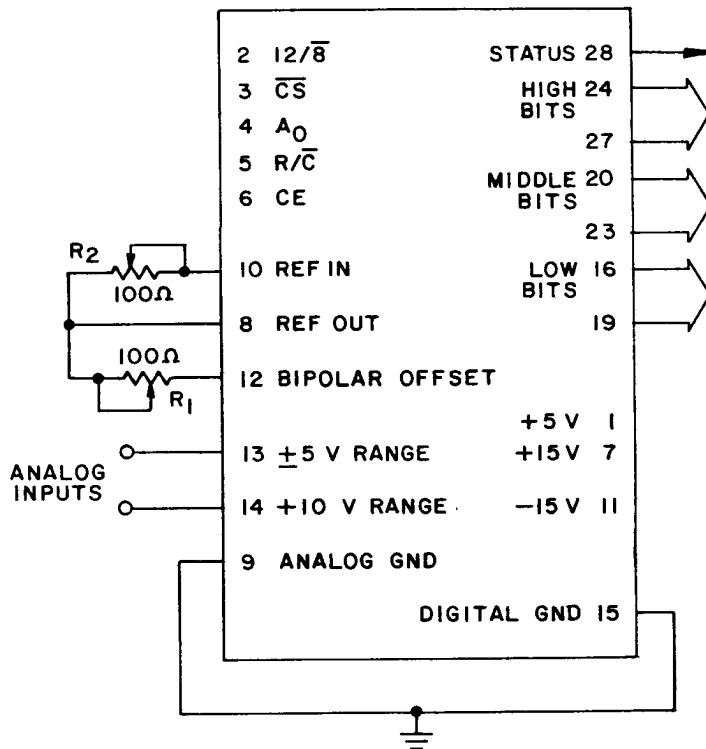
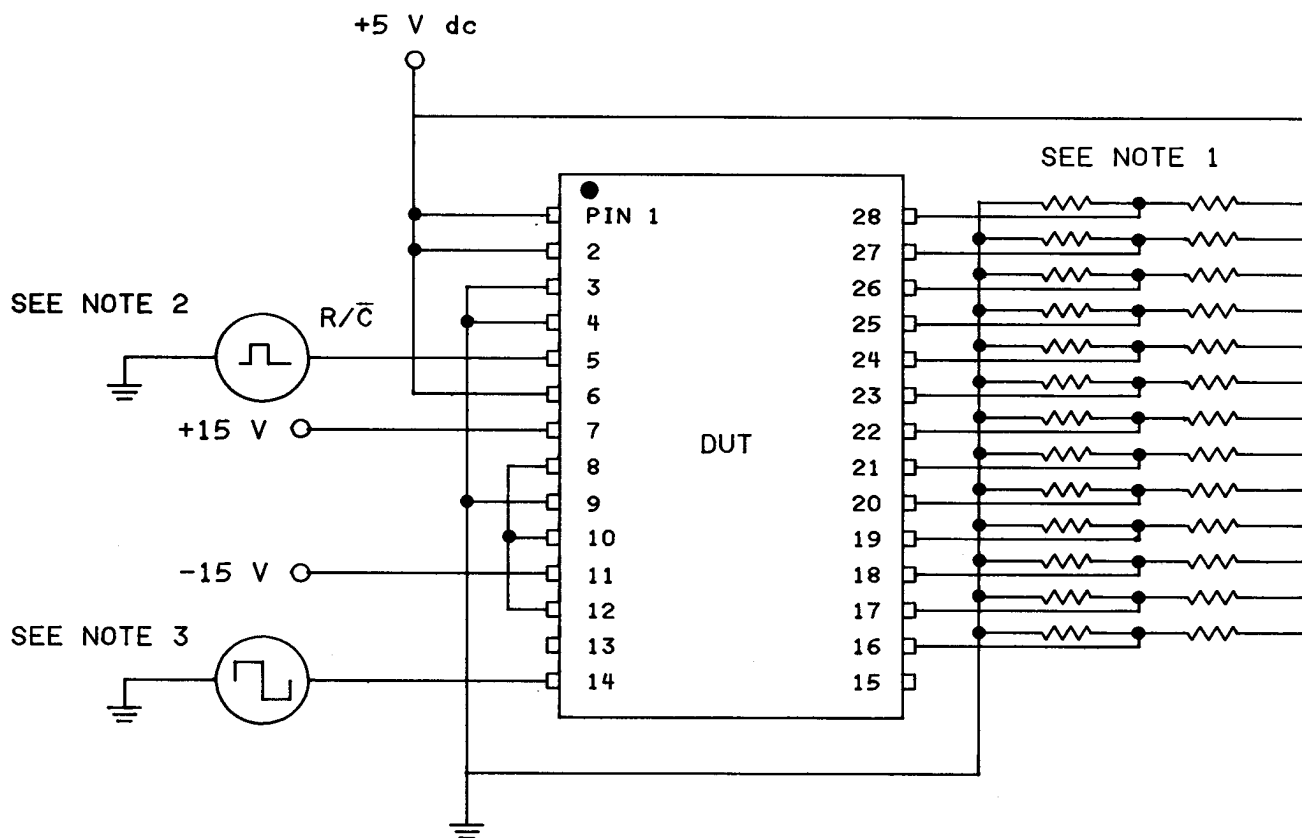


FIGURE 4. Functional schematics with application notes - Continued.

Input voltage range	Adjustment	Input voltage	Pot	Adjust pot to point where D.U.T. is just on the verge of switching between the two codes shown.
0 to +20V	ZERO	2.44mV	R ₁	000000000000 000000000001
	GAIN	19.9927V	R ₂	111111111110 111111111111
0 to +10V	ZERO	1.22mV	R ₁	000000000000 000000000001
	GAIN	9.9963V	R ₂	111111111110 111111111111

Input voltage range	Adjustment	Input voltage	Pot	Adjust pot to point where D.U.T. is just on the verge of switching between the two codes shown.
±5V	ZERO	-4.9988V	R ₁	000000000000 000000000001
	GAIN	4.9963V	R ₂	111111111110 111111111111
±10V	ZERO	-9.9976V	R ₁	000000000000 000000000001
	GAIN	9.9927V	R ₂	111111111110 111111111111

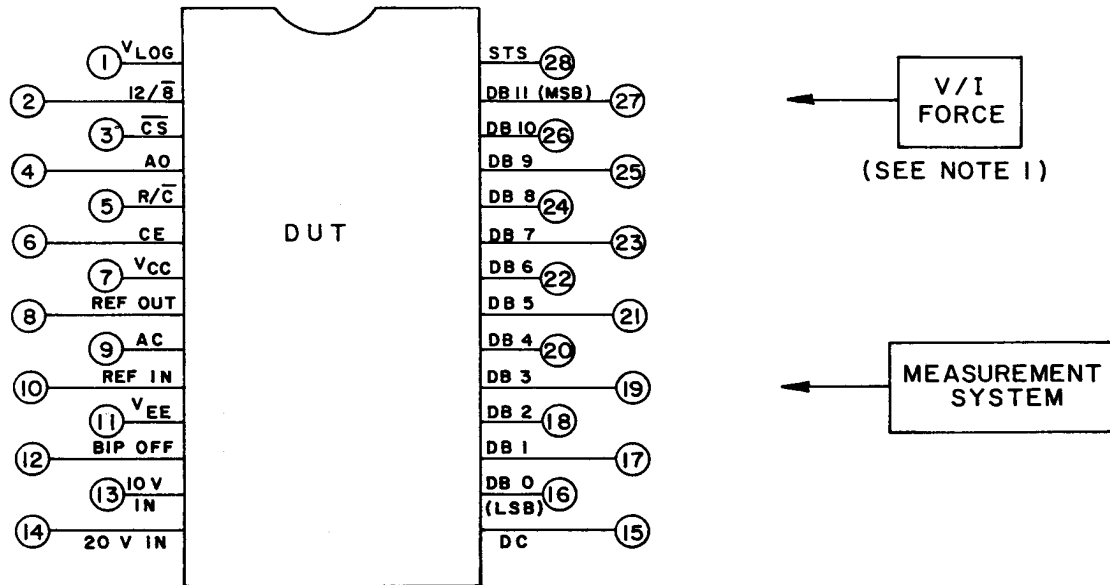
FIGURE 4. Functional schematics with application notes - Continued.



NOTES:

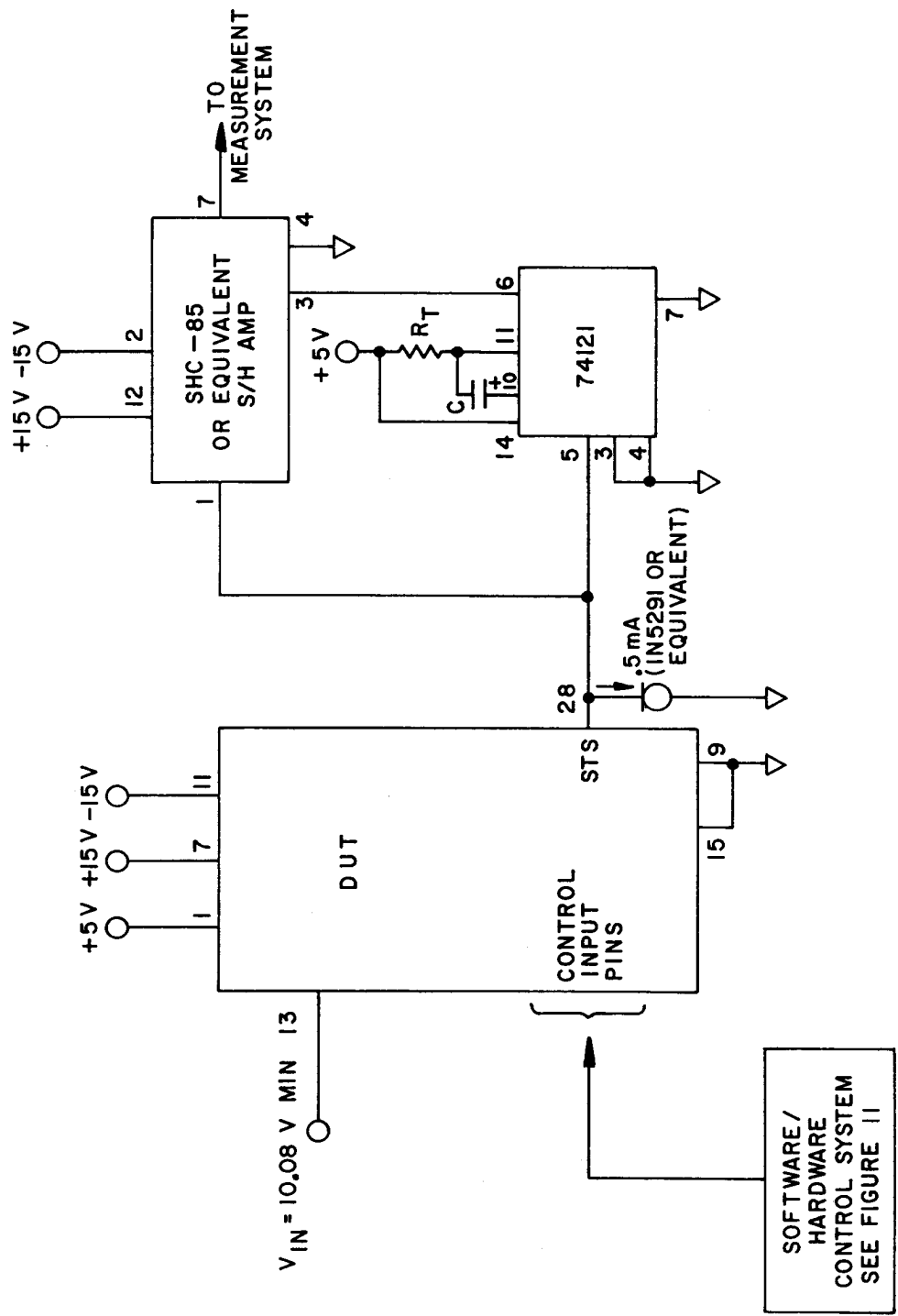
1. All resistors shall have a measured value of $3.0\text{ k}\Omega$, $\pm 1\%$, 1/4 watt and shall not exceed their branded value due to use, heat, or age.
2. Pulse width shall be $1\text{ }\mu\text{s}$ minimum.
Pulse repetition rate shall be 1 kHz .
Pulse levels shall be 0 V and 5 V .
3. Frequency shall be 60 Hz synchronized to the R/C pulse. Amplitude shall be $+10\text{ V}$ minimum and -10 V maximum.
4. One $10\text{ }\mu\text{F} \pm 20\%$ capacitor shall be connected from each voltage supply line to ground.

FIGURE 5. Test circuit for burn-in and steady state life test.



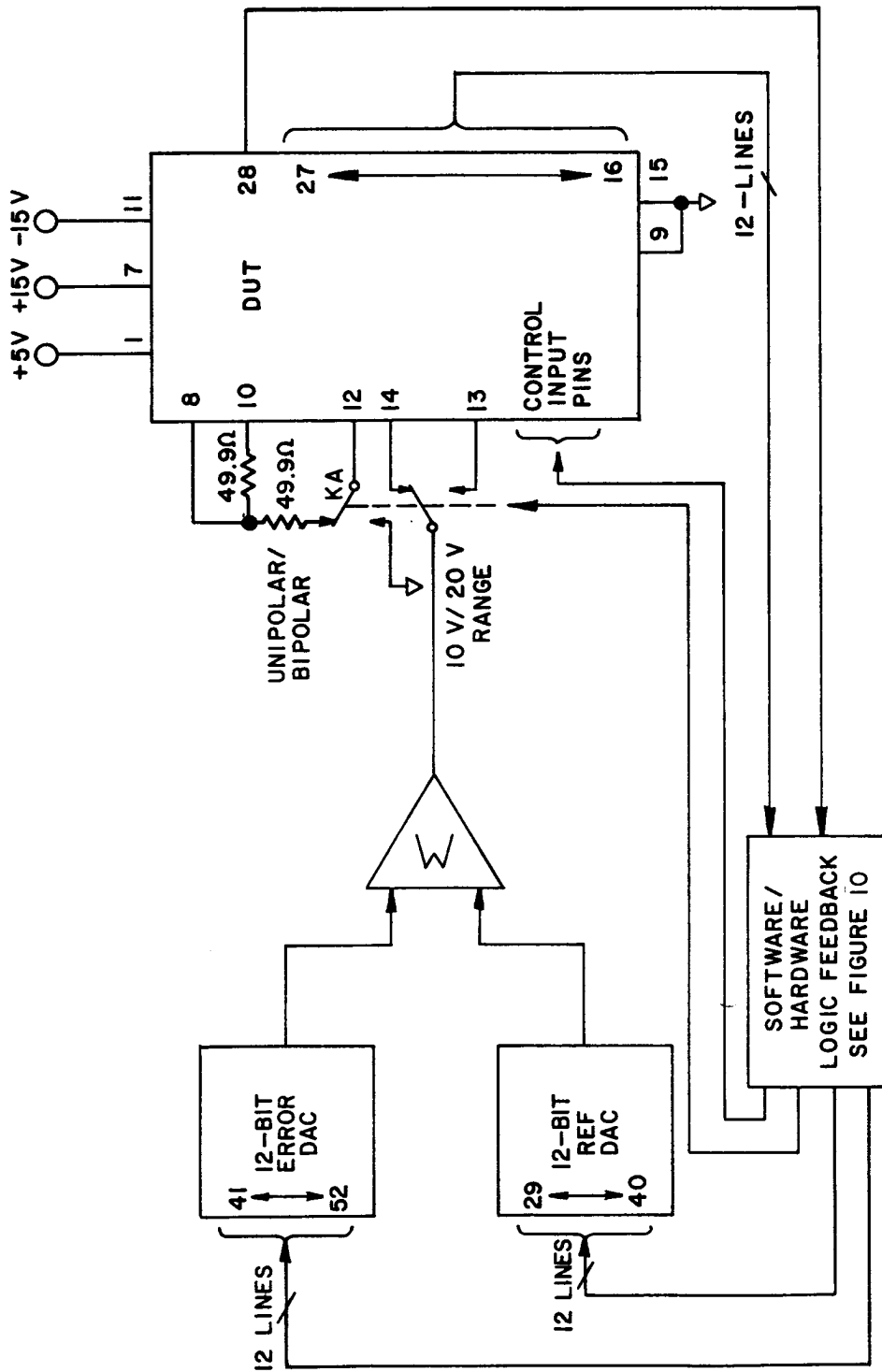
NOTE: The connections of the V/I force and measurement system are software controlled.

FIGURE 6. Test circuit for static test.



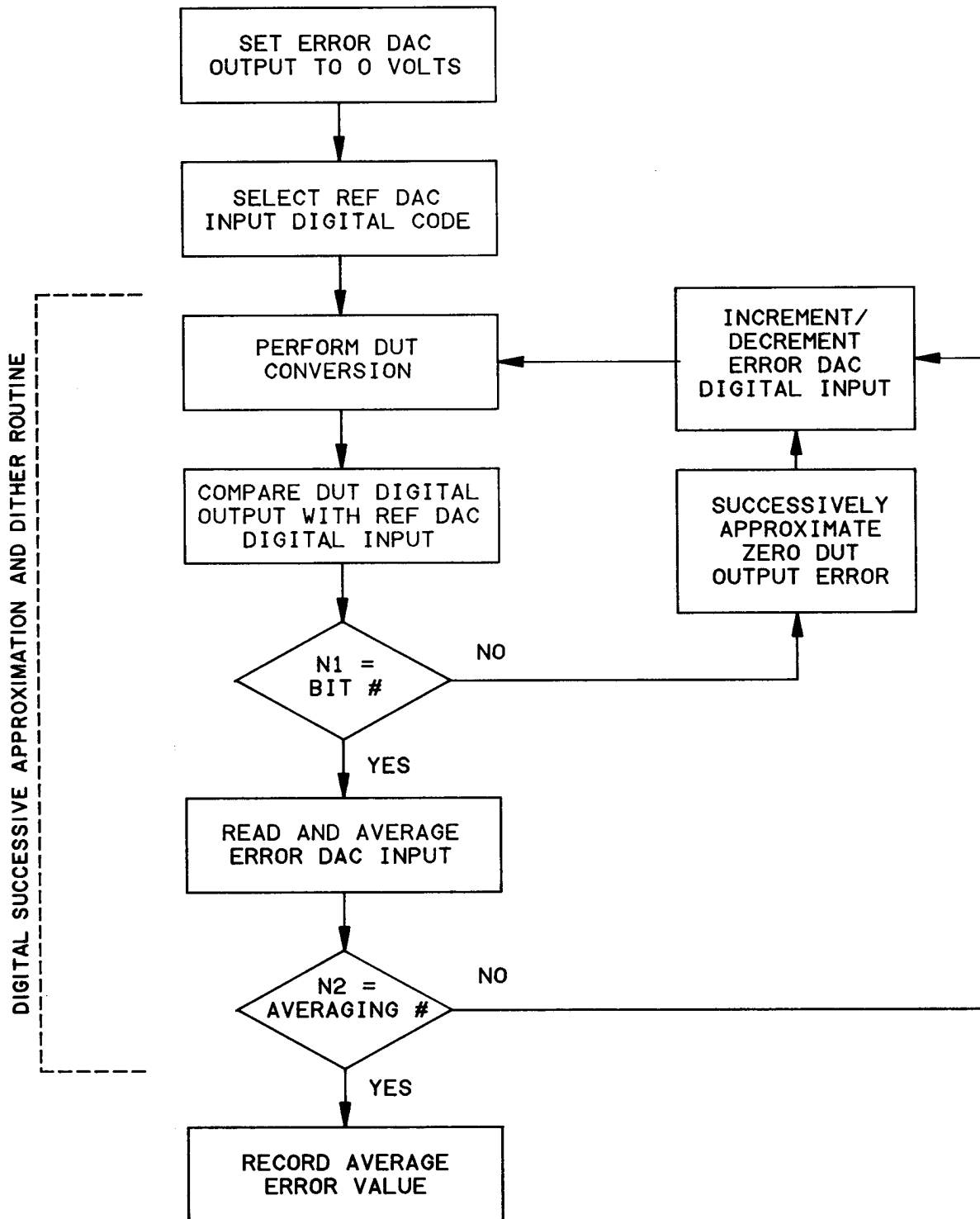
- NOTES:
- 1. R_T and C are selected for an 8.0 μs delay time interval.
 - 2. DUT test circuit shall be as defined in table I.

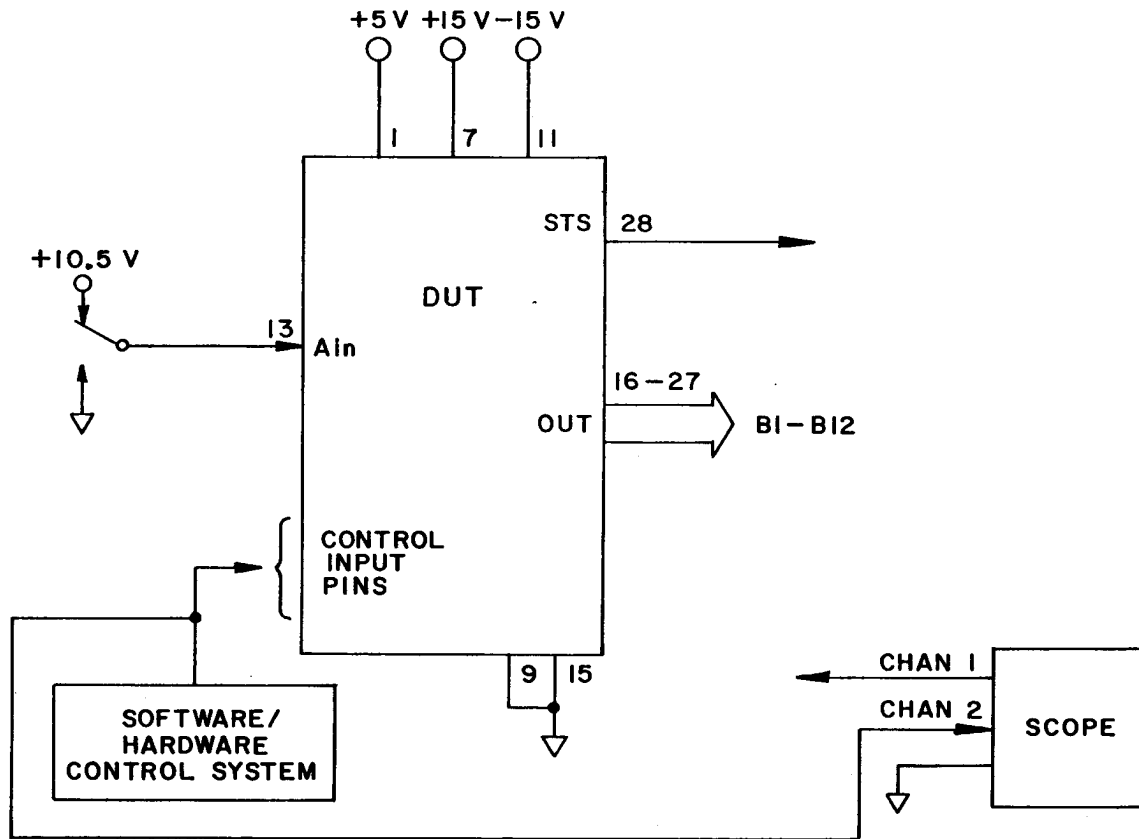
FIGURE 7. Output test circuit for measuring the STS logic "1" voltage level.

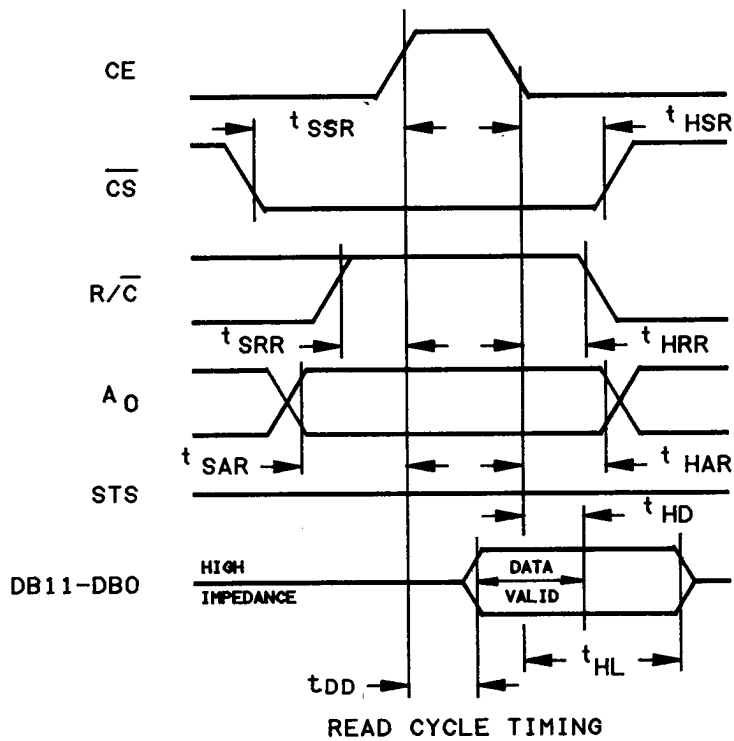
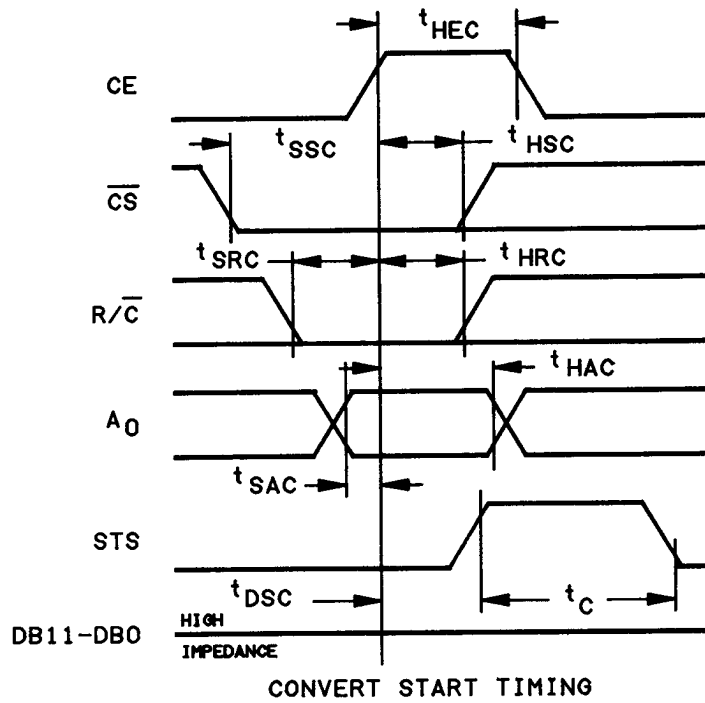


NOTE: The 12-bit ref DAC shall have an accuracy of 16-bits.

FIGURE 8. Test circuit for dynamic test.

FIGURE 8. Test circuit for dynamic test - Continued.

FIGURE 9. Test circuit for propagation delay.

FIGURE 10. Timing diagrams (system controlled operation).

Test setup timing specifications

CONVERT MODE

Symbol	Parameter	Min	Unit
t_{HEC}	CE Pulse width	300	ns
t_{SSC}	$\overline{CS}$ to CE Setup	300	"
t_{HSC}	$\overline{CS}$ Low during CE high	200	"
t_{SRC}	$R/\overline{C}$ to CE setup	250	"
t_{HRC}	$R/\overline{C}$ Low during CE high	200	"
t_{SAC}	A_0 to CE Setup	0	"
t_{HAC}	A_0 valid during CE high	300	"

READ MODE

Symbol	Parameter	Min	Unit
t_{SSR}	$\overline{CS}$ to CE Setup	150	ns
t_{SRR}	$R/\overline{C}$ to CE Setup	0	"
t_{SAR}	A_0 to CE Setup	150	"
t_{HSR}	$\overline{CS}$ Valid after CE low	50	"
t_{HRR}	$R/\overline{C}$ High after CE low	0	"
t_{HAR}	A_0 Valid after CE low	50	"

NOTE:

1. Test parameter t_{DD} is measured with the following load circuit and the access time is defined as the time required for an output to reach 0.4 V and 2.4 V for V_{OL} and V_{OH} , respectively.
2. Test parameters t_{HL} and t_{HD} are measured with the following load circuit and the float delay time are defined as the time required for an output to reach 0.8 V and 2.0 V from a logic "0" and from a logic "1", respectively.

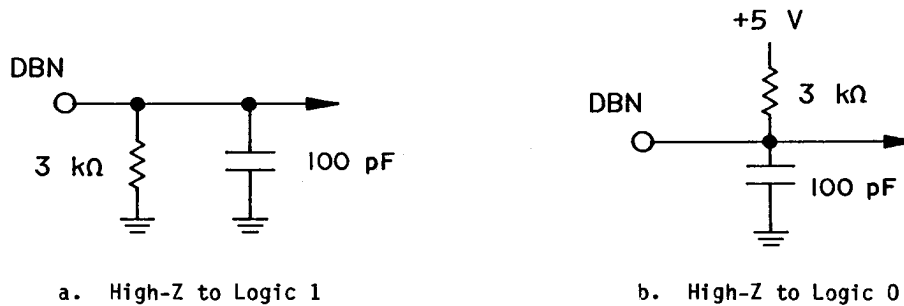
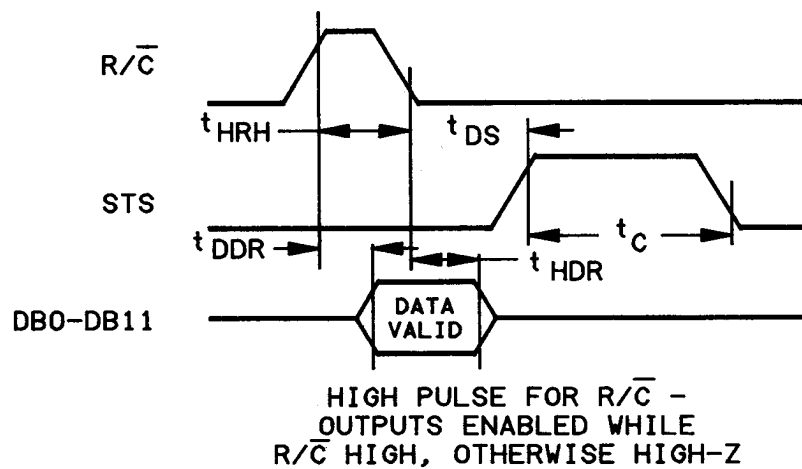
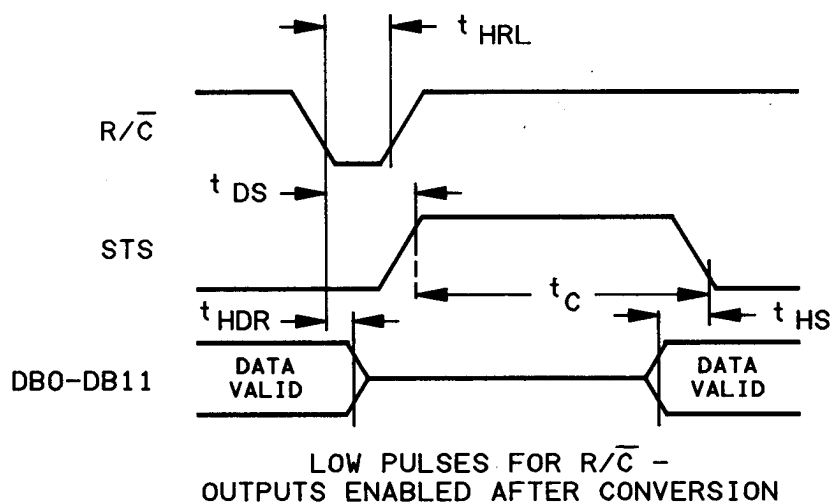


FIGURE 10. Timing diagrams (system controlled operation) - Continued.

FIGURE 11. Timing diagrams (stand alone operation).

Test setup timing specifications

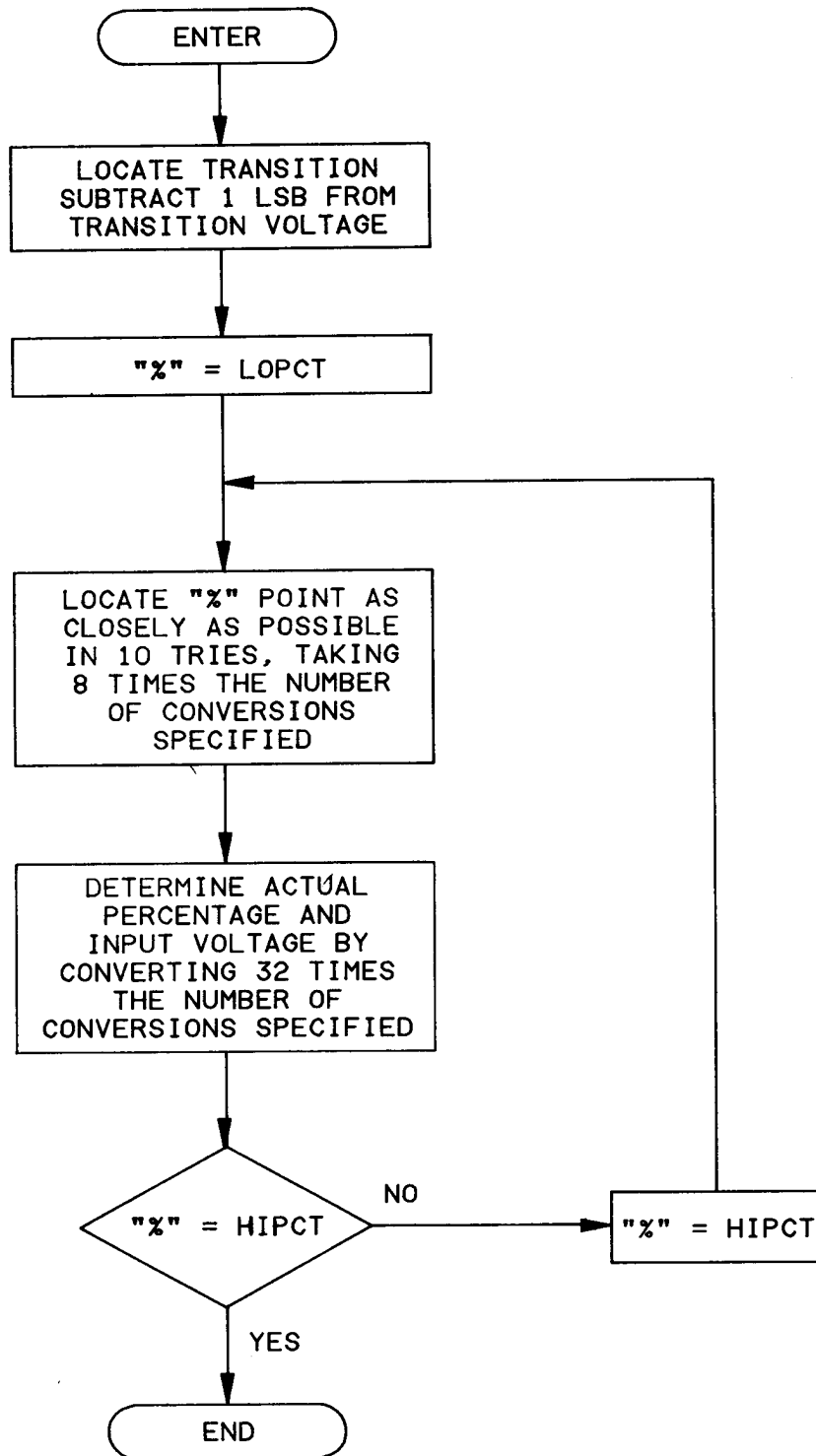
STAND ALONE MODE

Symbol	Parameter	Min	Unit
t_{HRL}	Low $R/\bar{C}$ pulse width	350	ns
t_{HRH}	High $R/\bar{C}$ pulse width	250	"

NOTE: For stand-alone operation, CE is tied to logic "1",
 $\overline{12/8}$ is wired to +5 V, and
 CS and A_0 are tied to logic "0".

Test parameter t_{RR} is measured with the following load circuit and the access time is defined as the time required for an output to reach 0.4 V and 2.4 V for V_{OL} and V_{OH} , respectively.
 Test parameter t_{HQR} is measured with the following load circuit and the float delay time is defined as the time required for an output to reach 0.8 V and 2.0 V from a logic "0" and from a logic "1", respectively.

FIGURE 11. Timing diagrams (stand alone operation) - Continued.



NOTE: The transition uncertainty is measured from the point where 16% of the measured values are skewed to the left to a point where 16% of the measured values are skewed to the right.

FIGURE 12. Algorithm for measuring transition uncertainty.

TABLE III. Group A Inspection for all device types.

Subgroup	Symbol	Test no.	Applied voltages ref. pin 9 (figures 6, 10)				DUT digital output code-word	Measurement sense lines ref. pin 9			Equations and notes	Limits		Units
			7	11	13	1		Pin	Value	Unit		Min	Max	
1 $T_A = 25^\circ\text{C}$	I _{CC1} I _{CC2}	1 2	+15.0 "	-15.0 "	Max (-) Max (+)	+5.0 "	0000 0000 0000 1111 1111 1111	7 7	I ₁ I ₂	mA	All device types	1 1	16 16	mA
	I _{EE1} I _{EE2}	3 4	" "	" "	Max (-) Max (+)	" "	0000 0000 0000 1111 1111 1111	11 11	I ₃ I ₄	"	" "	-30 -30	-1 -1	" "
	I _{L0G1} I _{L0G2}	5 6	" "	" "	Max (-) Max (+)	" "	0000 0000 0000 1111 1111 1111	1 1	I ₁₅ I ₁₆	"	" "	1 1	40 40	" "
	P _{d1} P _{d2}	7 8	" "	" "	Max (-) Max (+)	" "	0000 0000 0000 1111 1111 1111				$P_{d1} = I_{CC1} * V_{CC} + I_{EE1} * V_{EE} + I_{L0G1} * V_{L0G}$ $P_{d2} = I_{CC2} * V_{CC} + I_{EE2} * V_{EE} + I_{L0G2} * V_{L0G}$	---	725 725	mW mW
	I _{L11} I _{L12} I _{L13} I _{L14}	9 10 11 12	" " " "	" " " "	---	" " " "	---	3 4 5 6	I ₁₇ I ₁₈ I ₁₉ I ₁₁₀	mA	$V_{IN}(logic) = 0.0\text{ V}$ All device types	-10 "	1 "	μA "
	I _{IH1} I _{IH2} I _{IH3} I _{IH4}	13 14 15 16	" " " "	" " " "	" " " "	" " " "	" " " "	3 4 5 6	I ₁₁₁ I ₁₁₂ I ₁₁₃ I ₁₁₄	μA	$V_{IN}(logic) = 2.4\text{ V}$ All device types	-1 "	10 "	" "
	I _{IH5} I _{IH6} I _{IH7} I _{IH8}	17 18 19 20	" " " "	" " " "	" " " "	" " " "	" " " "	3 4 5 6	I ₁₁₅ I ₁₁₆ I ₁₁₇ I ₁₁₈	"	$V_{IN}(logic) = 5.5\text{ V}$ All device types	" "	" "	" "
	I _{ZL1} I _{ZL2} I _{ZL3} I _{ZL4} I _{ZL5} I _{ZL6} I _{ZL7} I _{ZL8} I _{ZL9} I _{ZL10} I _{ZL11} I _{ZL12}	21 22 23 24 25 26 27 28 29 30 31 32	" " " " " " " " " " "	+5.5 V " " " " " " " " "	Max (+) " " " " " " " "	" " " " " " " " "	1111 1111 1111 " " " " " " " "	16 17 18 19 20 21 22 23 24 25 26 27	I ₁₁₉ I ₁₂₀ I ₁₂₁ I ₁₂₂ I ₁₂₃ I ₁₂₄ I ₁₂₅ I ₁₂₆ I ₁₂₇ I ₁₂₈ I ₁₂₉ I ₁₃₀	"	$V_0 = 0.0\text{ V}$ $V_{R/C} = logic\ "0"$ All device types	-10 "	10 "	" "
	I _{ZH1} I _{ZH2} I _{ZH3} I _{ZH4} I _{ZH5} I _{ZH6} I _{ZH7} I _{ZH8} I _{ZH9} I _{ZH10} I _{ZH11} I _{ZH12}	33 34 35 36 37 38 39 40 41 42 43 44	" " " " " " " " " " "	" " " " " " " " "	Max (-) " " " " " " " "	" " " " " " " "	0000 0000 0000 " " " " " " "	16 17 18 19 20 21 22 23 24 25 26 27	I ₁₃₁ I ₁₃₂ I ₁₃₃ I ₁₃₄ I ₁₃₅ I ₁₃₆ I ₁₃₇ I ₁₃₈ I ₁₃₉ I ₁₄₀ I ₁₄₁ I ₁₄₂	"	$V_0 = 5.5\text{ V}$ $V_{R/C} = logic\ "0"$ All device types	" "	" "	" "

TABLE III. Group A inspection for all device types - Continued.

Subgroup	Symbol	Test no.	Applied voltages ref. pin 9 (figures 6, 10)				DUT digital output code-word	Measurement sense lines ref. pin no. 9			Equations and notes	Limits		Units
			7 V_{CC} (V)	11 V_{EE} (V)	1 V_{DD} (V)	13 $V_{IN(a)}$ (V)		Pin	Value	Unit		Min	Max	
1 $T_A = 25^\circ\text{C}$	tc1	45	+15.0	-15.0	+5.0	Max (-)	0000 0000 0000	28	t1	s	8-bit cycle device types 01, 02, 03, 04 device types 05, 06 12-bit cycle device types 01, 02, 03, 04 device types 05, 06	10	29	μs
	tc2	46	"	"	"	"	0000 0000 0000	28	t2	s		15	11.5	"
	VOL1	47	"	"	+4.5	"	"	16	E1	V	$I_L = 1.6\text{ mA}$ $V_{R/C} = \text{logic "0"} \rightarrow \text{"1"}$ All device types	0.4	"	V
	VOL2	48	"	"	"	"	"	17	E2	"		"	"	"
	VOL3	49	"	"	"	"	"	18	E3	"		"	"	"
	VOL4	50	"	"	"	"	"	19	E4	"		"	"	"
	VOL5	51	"	"	"	"	"	20	E5	"		"	"	"
	VOL6	52	"	"	"	"	"	21	E6	"		"	"	"
	VOL7	53	"	"	"	"	"	22	E7	"		"	"	"
	VOL8	54	"	"	"	"	"	23	E8	"		"	"	"
	VOL9	55	"	"	"	"	"	24	E9	"		"	"	"
	VOL10	56	"	"	"	"	"	25	E10	"		"	"	"
	VOL11	57	"	"	"	"	"	26	E11	"		"	"	"
	VOL12	58	"	"	"	"	"	27	E12	"		"	"	"
	VOL13	59	"	"	"	"	"	28	E13	"		"	"	"
	VOH1	60	"	"	"	Max (+)	1111 1111 1111	16	E14	"	$I_L = -0.5\text{ mA}$ $V_{R/C} = \text{logic "0"} \rightarrow \text{"1"}$ All device types	2.4	"	V
	VOH2	61	"	"	"	"	"	17	E15	"		"	"	"
	VOH3	62	"	"	"	"	"	18	E16	"		"	"	"
	VOH4	63	"	"	"	"	"	19	E17	"		"	"	"
	VOH5	64	"	"	"	"	"	20	E18	"		"	"	"
	VOH6	65	"	"	"	"	"	21	E19	"		"	"	"
	VOH7	66	"	"	"	"	"	22	E20	"		"	"	"
	VOH8	67	"	"	"	"	"	23	E21	"		"	"	"
	VOH9	68	"	"	"	"	"	24	E22	"		"	"	"
	VOH10	69	"	"	"	"	"	25	E23	"		"	"	"
	VOH11	70	"	"	"	"	"	26	E24	"		"	"	"
	VOH12	71	"	"	"	"	"	27	E25	"		"	"	"
	VOH13	72	"	"	"	"	"	28	E26	"	(Figures 8, 9, 12)	"	"	"
	VREF	73	"	"	+5.0	Max (-)	0000 0000 0000	8	E27	"	Bipolar, $V_{ESR} = 20\text{ V}$ $I_L = 1.5\text{ mA}$ device types 01, 02 03, 04, 05, 06	9.95	10.05	"
												9.90	10.10	"
	m1	74	"	"	"	Max (+)	1111 1111 XXXX	27	E28	"	$I_L = -0.5\text{ mA}$ $V_{I2/8} = 0.0\text{ V}$ $V_{AO} = \text{logic "0"}$ $V_{R/C} = \text{logic "0"} \rightarrow \text{"1"}$ All device types	2.4	"	"
		75	"	"	"	"	"	26	E29	"		"	"	"
		76	"	"	"	"	"	25	E30	"		"	"	"
		77	"	"	"	"	"	24	E31	"		"	"	"
		78	"	"	"	"	"	23	E32	"		"	"	"
		79	"	"	"	"	"	22	E33	"		"	"	"
		80	"	"	"	"	"	21	E34	"		"	"	"
		81	"	"	"	"	"	20	E35	"		"	"	"
	m2	82	"	"	"	"	XXXX 0000 1111	19	E36	"	$I_L = -0.5\text{ mA}$ $V_{CE} = \text{logic "0"}$ $V_{AO} = \text{logic "1"}$ $V_{CE} = \text{logic "1"}$ All device types	2.4	"	"
		83	"	"	"	"	"	18	E37	"		"	"	"
		84	"	"	"	"	"	17	E38	"		"	"	"
		85	"	"	"	"	"	16	E39	"		"	"	"
	m3	86	"	"	"	"	"	23	E40	"	$I_L = 1.6\text{ mA}$ All device types	0.4	"	"
		87	"	"	"	"	"	22	E41	"		"	"	"
		88	"	"	"	"	"	21	E42	"		"	"	"
		89	"	"	"	"	"	20	E43	"		"	"	"

TABLE III. Group A inspection for all device types - Continued.

Subgroup	Symbol	Test no.	Applied voltages ref. pin 9 (figures 6, 10)				DUT digital output code-word	Measurement sense lines ref. pin 9		Equations and notes	Limits		Units
			7 V_{CC} (V)	11 V_{EE} (V)	1 V_{DD} (V)	13 $V_{IN(a)}$ (V)		Pin	Unit		Min	Max	
1 $T_A = 25^\circ\text{C}$	I_{m4}	90	+15.0	-15.0	+5.0	Max (+)	XXXX 0000 1111	27	143	$I_{m4} = 143$	-10	10	μA
		91	"	"	"	"	"	26	144	$I_{m4b} = 144$	"	"	"
		92	"	"	"	"	"	25	145	$I_{m4c} = 145$	"	"	"
		93	"	"	"	"	"	24	146	$I_{m4d} = 146$	"	"	"
	I_{m5}	94	"	"	"	"	1111 1111 XXXX	19	147	$I_{m5a} = 147$	"	"	"
		95	"	"	"	"	"	18	148	$I_{m5b} = 148$	"	"	"
		96	"	"	"	"	"	17	149	$I_{m5c} = 149$	"	"	"
		97	"	"	"	"	"	16	150	$I_{m5d} = 150$	"	"	"
	$V_{R/C}$	98	"	"	"	Max (-)	0000 0000 0000	16	E44	$V_{R/C} = .8\text{ V (Init.)}$	(Logic "0")	"	
			"	"	"	"	"	17	E45	$V_{R/C} = 2.0\text{ V (Conv.)}$	"	"	
			"	"	"	"	"	18	E46	All device types	"	"	
	$V_{R/C}$	99	"	"	"	Max (+)	1111 1111 1111	16	E57	(Convert and read)	(Logic "1")	"	
			"	"	"	"	"	17	E58	$V_{R/C} = .8\text{ V (Init.)}$	"	"	
			"	"	"	"	"	18	E59	$V_{R/C} = 2.0\text{ V}$	"	"	
	V_{CE}	100	"	"	"	"	"	19	E60	All device types	"	"	
			"	"	"	"	"	20	E61	"	"	"	
			"	"	"	"	"	21	E62	"	"	"	
	V_{CE}	101	"	"	"	Max (-)	"	22	E63	(Convert and read)	"	"	
			"	"	"	"	"	23	E64	$V_{CE} = .8\text{ V (Init.)}$	"	"	
			"	"	"	"	"	24	E65	$V_{CE} = 2.0\text{ V}$	"	"	
	V_{CE}	102	"	"	"	"	"	25	E66	All device types	"	"	
			"	"	"	"	"	26	E67	"	"	"	
			"	"	"	"	"	27	E68	"	"	"	
	V_{CE}	103	"	"	"	"	"	28	E69	(Convert and read)	"	"	
			"	"	"	"	"	29	E70	$V_{CE} = .8\text{ V (Init.)}$	"	"	
			"	"	"	"	"	30	E71	$V_{CE} = 2.0\text{ V}$	"	"	
	V_{CE}	104	"	"	"	"	"	31	E72	All device types	"	"	
			"	"	"	"	"	32	E73	"	"	"	
			"	"	"	"	"	33	E74	"	"	"	
	V_{CE}	105	"	"	"	"	"	34	E75	(Convert and read)	"	"	
			"	"	"	"	"	35	E76	$V_{CE} = .8\text{ V (Init.)}$	"	"	
			"	"	"	"	"	36	E77	$V_{CE} = 2.0\text{ V}$	"	"	
	V_{CE}	106	"	"	"	"	"	37	E78	All device types	"	"	
			"	"	"	"	"	38	E79	"	"	"	
			"	"	"	"	"	39	E80	"	"	"	
	V_{CE}	107	"	"	"	"	"	40	E81	(Convert and read)	"	"	
			"	"	"	"	"	41	E82	$V_{CE} = .8\text{ V (Init.)}$	"	"	
			"	"	"	"	"	42	E83	$V_{CE} = 2.0\text{ V}$	"	"	
	V_{CE}	108	"	"	"	"	"	43	E84	All device types	"	"	
			"	"	"	"	"	44	E85	"	"	"	
			"	"	"	"	"	45	E86	"	"	"	
	V_{CE}	109	"	"	"	"	"	46	E87	(Convert and read)	"	"	
			"	"	"	"	"	47	E88	$V_{CE} = .8\text{ V (Init.)}$	"	"	
			"	"	"	"	"	48	E89	$V_{CE} = 2.0\text{ V}$	"	"	
	V_{CE}	110	"	"	"	"	"	49	E90	All device types	"	"	
			"	"	"	"	"	50	E91	"	"	"	
			"	"	"	"	"	51	E92	"	"	"	
	V_{CE}	111	"	"	"	"	"	52	E93	(Convert and read)	"	"	
			"	"	"	"	"	53	E94	$V_{CE} = .8\text{ V (Init.)}$	"	"	
			"	"	"	"	"	54	E95	$V_{CE} = 2.0\text{ V}$	"	"	

TABLE III. Group A Inspection for all device types - Continued.

Subgroup	Symbol	Test no.	Applied voltages ref. pin 9 (figures 6, 10)				DUT digital output code-word	Measurement sense lines ref. pin 9			Equations and notes	Limits		Units
			7 V_{CC} (V)	11 V_{EE} (V)	1 V_{DD} (V)	13 $V_{IN(a)}$ (V)		PIn	Value	Unit		Min	Max	
1 $T_A = 25^\circ\text{C}$	V_{CE}	102	$+15.0$	-15.0	$+5.0$	Max (-)	127<----->16 MSB<----->LSB	16	E96	V	All device types $V_{CE} = 2.0$ (convert and read)	(Logic "0")		
							0000 0000 0000	17	E97					
								18	E98					
								19	E99					
								20	E100					
								21	E101					
								22	E102					
								23	E103					
								24	E104					
								25	E105					
								26	E106					
								27	E107					
								28	E108					
	V_{CS}	103				Max (+)	1111 1111 1111	16	E109		All device types $V_{CS} = \text{logic "1"}$ $V_{CS} = 0.8$ V _{CC} (convert and read)	(Logic "1")		
								17	E110					
								18	E111					
								19	E112					
								20	E113					
								21	E114					
								22	E115					
								23	E116					
								24	E117					
								25	E118					
								26	E119					
								27	E120					
								28	E121					
		104				Max (-)		16	E122		All device types Set $V_{CS} = 2.0$ V Set $V_{IN(a)} = -7$ mV Set $V_{CE} = \text{logic "1"}$ (read)			
								17	E123					
								18	E124					
								19	E125					
								20	E126					
								21	E127					
								22	E128					
								23	E129					
								24	E130					
								25	E131					
								26	E132					
								27	E133					
								28	E134					
		105					0000 0000 0000	16	E135		All device types $V_{CS} = 0.8$ V (convert and read)	(Logic "0")		
								17	E136					
								18	E137					
								19	E138					
								20	E139					
								21	E140					
								22	E141					
								23	E142					
								24	E143					
								25	E144					
								26	E145					
								27	E146					
								28	E147					
	V_{AO}	106					1111 1111 XXXX	20	E148		All device types $V_{12/8} = 0.0$ V $V_{AO} = 0.8$ V _{CC} (convert and read)	(Logic "1")		
								21	E149					
								22	E150					
								23	E151					
		107					XXXX 0000 1111	20	E152		All device types $V_{CE} = \text{logic "0"}$ $V_{AO} = 2.0$ V _{CC} "1"	(Logic "0")		
								21	E153					
								22	E154					
								23	E155					

TABLE III. Group A inspection for all device types - Continued.

Subgroup	Symbol	Test no.	Applied voltages ref. pin 9 (figures 6, 10)			Applied digital code-word	DUT digital output code-word	Measurement sense lines ref. pin 9			Equations and notes	Limits		Units
			7 V_{CC} (V)	11 V_{EE} (V)	1 V_{DD} (V)			Pin	Value	Unit		Min	Max	
1 $T_A = 25^\circ\text{C}$	+PSS1	108	+15.0	-15.0	+5.0	10000 0000 0000	10000 0000 0000	13	E156	V	All device types +PSS1a = 41*(E156-E157) +PSS1b = 41*(E158-E159)	-10	+10	LSB/2PS
		109	+13.5	"	"	"	"	"	E157	"	"	"	"	"
		110	+15.0	"	"	1111 1111 1110	1111 1111 1111	"	E158	"	"	"	"	"
		111	+13.5	"	"	"	"	"	E159	"	"	"	"	"
		112	+15.0	"	"	"	"	"	E160	"	"	"	"	"
	+PSS2	113	+16.5	"	"	"	"	"	E161	"	"	"	"	"
		114	+12.0	-12.0	"	10000 0000 0000	10000 0000 0000	"	E162	"	All device types +PSS2a = 81.9*(E162-E163) +PSS2b = 81.9*(E164-E165)	-20	+20	"
		115	+11.4	"	"	"	"	"	E163	"	"	"	"	"
		116	+12.6	"	"	1111 1111 1110	1111 1111 1111	"	E164	"	"	"	"	"
		117	+11.4	"	"	"	"	"	E165	"	"	"	"	"
	+PSS3	118	+12.6	"	"	10000 0000 0000	10000 0000 0000	"	E166	"	All device types +PSS3a = 41*(E168-E169) +PSS3b = 41*(E170-E171)	-10	+10	"
		119	+15.0	-15.0	+4.5	"	"	"	E167	"	"	"	"	"
		120	"	"	+5.0	1111 1111 1110	1111 1111 1111	"	E168	"	"	"	"	"
		121	"	"	+4.5	"	"	"	E169	"	"	"	"	"
		122	"	"	+5.5	"	"	"	E170	"	"	"	"	"
2 $T_A = 125^\circ\text{C}$	-PSS1	123	"	"	"	10000 0000 0000	10000 0000 0000	"	E171	"	All device types -PSS1a = 41*(E174-E175) -PSS1b = 41*(E176-E177)	"	"	"
		124	+15.0	-15.0	+5.0	"	"	"	E172	"	"	"	"	"
		125	+12.0	-12.0	"	1111 1111 1110	1111 1111 1111	"	E173	"	"	"	"	"
		126	+11.4	-11.4	"	"	"	"	E174	"	"	"	"	"
		127	+12.6	-12.6	"	"	"	"	E175	"	"	"	"	"
	-PSS2	128	+15.0	-15.0	"	10000 0000 0000	10000 0000 0000	"	E176	"	All device types -PSS2a = 81.9*(E180-E181) -PSS2b = 81.9*(E182-E183)	-20	+20	"
		129	+12.0	-12.0	"	"	"	"	E177	"	"	"	"	"
		130	+11.4	-11.4	"	1111 1111 1110	1111 1111 1111	"	E178	"	"	"	"	"
		131	+12.6	-12.6	"	"	"	"	E179	"	"	"	"	"
		132	+15.0	-15.0	"	"	"	"	E180	"	"	"	"	"
3 $T_A = -55^\circ\text{C}$	(All test parameters, test conditions, equations and test limits in subgroup 2 are identical with those specified in table III, subgroup 1.)	133	+12.0	-12.0	"	10000 0000 0000	10000 0000 0000	"	E181	"	"	"	"	"
		134	+11.4	-11.4	"	"	"	"	E182	"	"	"	"	"
		135	+12.6	-12.6	"	1111 1111 1110	1111 1111 1111	"	E183	"	"	"	"	"

TABLE III. Group A inspection for all device types - Continued.

Subgroup	Symbol	Test no.	Applied voltages ref. pin 10 (figures 8, 10)			Applied digital code-word	DUT digital output code-word	Active relays	Measurement sense lines ref. pin 9		Equations and notes	Limits		Units
			V_{CC}	V_{EE}	V_{DD}				Pin	Unit		Min	Max	
$T_A = 25^\circ\text{C}$	V_{IO}	382	+15.0	-15.0	+5.0	29<----->40 MSB<----->LSB	29<----->40 MSB<----->LSB		13	ES56	Device types 01, 02 03, 04, 05, 06	-0.5	1.5	LSB
	B_Z	383	"	"	"	0111 1111 1111	6666 6666 6666	KA	"	ES57	All device types	-4.5	3.5	"
	A_E	384	"	"	"	0000 0000 0000 1111 1111 1110	0000 0000 0006 1111 1111 1116	"	"	ES58 ES59	Device type 01 Device type 02 03, 04, 05, 06	-125 -25 -3	125 25 10.3	%FSR " "
	B_{PAE}	385	"	"	"	0000 0000 0000 1111 1111 1110	0000 0000 0006 1111 1111 1116	KA	"	ES60 ES61	$B_{PAE} = 100 \times (19,990 \times (E560 - E559) / (E560 - E559))$	-0.125 -0.25 -0.3	0.125 0.25 10.3	" " "
	L_{E1}	386	"	"	"	1111 1111 1110	1111 1111 1116	"	"	ES62	For end-point linearity error, $L_{E(N)} = ((E(N+562) + E(N+563)) / 2 - V_{ideal}) / S$ $V_{ideal} = (E(N+562) + E(N+563)) / 2$ code-word: S = (E563-E563)/4094	-5	5	LSB
	L_{E2}	387	"	"	"	0000 0000 0000	0000 0000 0006	"	"	ES63	All device types	"	"	"
	L_{E3}	388	"	"	"	0000 0000 0010	0000 0000 0016	"	"	ES64	$L_{E1} = ((E563 + E564) / 2 - 1 \times S - E563) \times S(2) / S$	"	"	"
	L_{E4}	389	"	"	"	0000 0000 0011	0000 0000 0016	"	"	ES65	$L_{E2} = ((E564 + E565) / 2 - 2 \times S - E563) \times S(2) / S$	"	"	"
	L_{E5}	390	"	"	"	0000 0000 0100	0000 0000 0106	"	"	ES66	$L_{E3} = ((E566 + E567) / 2 - 4 \times S - E563) \times S(2) / S$	"	"	"
	L_{E6}	391	"	"	"	0000 0000 0111	0000 0000 0116	"	"	ES67	$L_{E4} = ((E568 + E569) / 2 - 8 \times S - E563) \times S(2) / S$	"	"	"
	L_{E7}	392	"	"	"	0000 0010 0000	0000 0010 0006	"	"	ES68	$L_{E5} = ((E570 + E571) / 2 - 16 \times S - E563) \times S(2) / S$	"	"	"
	L_{E8}	393	"	"	"	0000 0011 0000	0000 0011 0006	"	"	ES69	$L_{E6} = ((E572 + E573) / 2 - 32 \times S - E563) \times S(2) / S$	"	"	"
	L_{E9}	394	"	"	"	0000 0100 0000	0000 0100 0006	"	"	ES70	$L_{E7} = ((E574 + E575) / 2 - 64 \times S - E563) \times S(2) / S$	"	"	"
	L_{E10}	395	"	"	"	0000 0111 0000	0000 0111 0006	"	"	ES71	$L_{E8} = ((E576 + E577) / 2 - 128 \times S - E563) \times S(2) / S$	"	"	"
	L_{E11}	396	"	"	"	0000 1000 0000	0000 1000 0006	"	"	ES72	$L_{E9} = ((E578 + E579) / 2 - 256 \times S - E563) \times S(2) / S$	"	"	"
	L_{E12}	397	"	"	"	0000 1001 0000	0000 1001 0006	"	"	ES73	$L_{E10} = ((E580 + E581) / 2 - 512 \times S - E563) \times S(2) / S$	"	"	"
	L_{E13}	398	"	"	"	0000 1010 0000	0000 1010 0006	"	"	ES74	$L_{E11} = ((E582 + E583) / 2 - 768 \times S - E563) \times S(2) / S$	"	"	"
	L_{E14}	399	"	"	"	0000 1011 0000	0000 1011 0006	"	"	ES75	$L_{E12} = ((E584 + E585) / 2 - 1024 \times S - E563) \times S(2) / S$	"	"	"
	L_{E15}	400	"	"	"	0000 1011 0001	0000 1011 0006	"	"	ES76	$L_{E13} = ((E586 + E587) / 2 - 1280 \times S - E563) \times S(2) / S$	"	"	"
	L_{E16}	401	"	"	"	0000 1011 0010	0000 1011 0006	"	"	ES77	$L_{E14} = ((E588 + E589) / 2 - 1536 \times S - E563) \times S(2) / S$	"	"	"
	L_{E17}	402	"	"	"	0000 1011 0011	0000 1011 0006	"	"	ES78	$L_{E15} = ((E590 + E591) / 2 - 1792 \times S - E563) \times S(2) / S$	"	"	"
	L_{E18}	403	"	"	"	0000 1011 0011	0000 1011 0006	"	"	ES79	$L_{E16} = ((E592 + E593) / 2 - 2048 \times S - E563) \times S(2) / S$	"	"	"
	L_{E19}	404	"	"	"	0000 1011 0011	0000 1011 0006	"	"	ES80	$L_{E17} = ((E594 + E595) / 2 - 2304 \times S - E563) \times S(2) / S$	"	"	"
	L_{E20}	405	"	"	"	0000 1011 0011	0000 1011 0006	"	"	ES81	$L_{E18} = ((E596 + E597) / 2 - 2560 \times S - E563) \times S(2) / S$	"	"	"
	L_{E21}	406	"	"	"	0000 1011 0011	0000 1011 0006	"	"	ES82	$L_{E19} = ((E598 + E599) / 2 - 2816 \times S - E563) \times S(2) / S$	"	"	"
	L_{E22}	407	"	"	"	0000 1011 0011	0000 1011 0006	"	"	ES83	$L_{E20} = ((E600 + E601) / 2 - 3072 \times S - E563) \times S(2) / S$	"	"	"
	L_{E23}	408	"	"	"	0000 1011 0011	0000 1011 0006	"	"	ES84	$L_{E21} = ((E602 + E603) / 2 - 3328 \times S - E563) \times S(2) / S$	"	"	"
	L_{E24}	409	"	"	"	0000 1011 0011	0000 1011 0006	"	"	ES85	$L_{E22} = ((E604 + E605) / 2 - 3584 \times S - E563) \times S(2) / S$	"	"	"
	L_{E25}	410	"	"	"	0000 1011 0011	0000 1011 0006	"	"	ES86	$L_{E23} = ((E606 + E607) / 2 - 3840 \times S - E563) \times S(2) / S$	"	"	"
	L_{E26}	411	"	"	"	0000 1011 0011	0000 1011 0006	"	"	ES87	$L_{E24} = ((E608 + E609) / 2 - 3968 \times S - E563) \times S(2) / S$	"	"	"
	L_{E27}	412	"	"	"	0000 1011 0011	0000 1011 0006	"	"	ES88	$L_{E25} = ((E610 + E611) / 2 - 4032 \times S - E563) \times S(2) / S$	"	"	"
	L_{E28}	413	"	"	"	0000 1011 0011	0000 1011 0006	"	"	ES89	$L_{E26} = ((E612 + E613) / 2 - 4064 \times S - E563) \times S(2) / S$	"	"	"
	L_{E29}	414	"	"	"	0000 1011 0011	0000 1011 0006	"	"	ES90	$L_{E27} = ((E614 + E615) / 2 - 4080 \times S - E563) \times S(2) / S$	"	"	"
	L_{E30}	415	"	"	"	0000 1011 0011	0000 1011 0006	"	"	ES91	$L_{E28} = ((E616 + E617) / 2 - 4096 \times S - E563) \times S(2) / S$	"	"	"

TABLE III. Group A inspection for all device types - Continued.

Subgroup	Symbol	Test no.	Applied voltages ref. pin 9 (figures 8, 10)			Applied digital code-word	DUT digital output code-word	Active relays	Measurement sense lines ref. pin 9		Equations and notes	Limits		Units
			7 V_{CC}	11 V_{EE}	1 V_{DD}	29<----->40 MSB<----->LSB	29<----->40 MSB<----->LSB		Pin	Value		Min	Max	
4 $T_A = 25^\circ\text{C}$	D_{LE1} D_{LE2} D_{LE3} D_{LE4} D_{LE5} D_{LE6} D_{LE7} D_{LE8} D_{LE9} D_{LE10} D_{LE11} D_{LE12} D_{LE13} D_{LE14} D_{LE15} D_{LE16} D_{LE17} D_{LE18} D_{LE19} D_{LE20} D_{LE21} D_{LE22} D_{LE23} D_{LE24} D_{LE25} D_{LE26} D_{LE27} D_{LE28} D_{LE29} D_{LE30}	416	+15.0	-15.0	+5.0	0000 0000 0001	0000 0000 0000	KA	13	V	For differential linearity error, $D_{LE}(N) = (E(N+563) - E(N+562))/S$ $S = (562-E563)/4094$, All device types	-9	1.0	LSB
		417	"	"	"	0000 0000 0010	0000 0000 0010	"	"	"	$D_{LE1} = (E564-E563)/S$	"	"	"
		418	"	"	"	0000 0000 0011	0000 0000 0011	"	"	"	$D_{LE2} = (E565-E564)/S$	"	"	"
		419	"	"	"	0000 0000 0100	0000 0000 0100	"	"	"	$D_{LE3} = (E566-E565)/S$	"	"	"
		420	"	"	"	0000 0000 1000	0000 0000 1000	"	"	"	$D_{LE4} = (E567-E566)/S$	"	"	"
		421	"	"	"	0000 0001 0000	0000 0001 0000	"	"	"	$D_{LE5} = (E571-E570)/S$	"	"	"
		422	"	"	"	0000 0010 0000	0000 0010 0000	"	"	"	$D_{LE6} = (E572-E571)/S$	"	"	"
		423	"	"	"	0000 0100 0000	0000 0100 0000	"	"	"	$D_{LE7} = (E573-E572)/S$	"	"	"
		424	"	"	"	0000 1000 0000	0000 1000 0000	"	"	"	$D_{LE8} = (E574-E573)/S$	"	"	"
		425	"	"	"	0001 0000 0000	0001 0000 0000	"	"	"	$D_{LE9} = (E575-E574)/S$	"	"	"
		426	"	"	"	0010 0000 0000	0010 0000 0000	"	"	"	$D_{LE10} = (E581-E580)/S$	"	"	"
		427	"	"	"	0011 0000 0000	0011 0000 0000	"	"	"	$D_{LE11} = (E582-E581)/S$	"	"	"
		428	"	"	"	0100 0000 0000	0100 0000 0000	"	"	"	$D_{LE12} = (E583-E582)/S$	"	"	"
		429	"	"	"	0101 0000 0000	0101 0000 0000	"	"	"	$D_{LE13} = (E584-E583)/S$	"	"	"
		430	"	"	"	0110 0000 0000	0110 0000 0000	"	"	"	$D_{LE14} = (E585-E584)/S$	"	"	"
		431	"	"	"	0111 0000 0000	0111 0000 0000	"	"	"	$D_{LE15} = (E586-E585)/S$	"	"	"
		432	"	"	"	1000 0000 0000	1000 0000 0000	"	"	"	$D_{LE16} = (E587-E586)/S$	"	"	"
		433	"	"	"	1001 0000 0000	1001 0000 0000	"	"	"	$D_{LE17} = (E588-E587)/S$	"	"	"
		434	"	"	"	1010 0000 0000	1010 0000 0000	"	"	"	$D_{LE18} = (E589-E588)/S$	"	"	"
		435	"	"	"	1011 0000 0000	1011 0000 0000	"	"	"	$D_{LE19} = (E591-E590)/S$	"	"	"
5 $T_A = 125^\circ\text{C}$	M_{CC} d_{VIO}/dT d_{PT}/dT d_{AF}/dT d_{BPAE}/dT	446	"	"	"	$V_{IN}(\text{analog}) =$ Max (-) through Max (+)	0000 0000 0000 through 1111 1111 1111				$M_{CC} =$ number of missing output codes from 0000 0000 0000 to 1111 1111 1111. (Figures 6, 7), all device types	0		Codes
		447	"	"	"	0000 0000 0000	0000 0000 0000		13	E622	$d_{VIO} = 410^\circ \text{ (E622-E556) } /dT$	-0.5 -1.0	0.5 1.0	LSB
		448	"	"	"	0111 1111 1111	0111 1111 1111	KA	"	E623	$d_{PT} = 410^\circ \text{ (E623-E557) } /dT$	-1.0 -2.0	1.0 2.0	"
		449	"	"	"	0000 0000 0000 1111 1111 1110	0000 0000 0000 1111 1111 1110		"	E624 E625	$d_{AF} = 9.995 \times 10^6 \times \left(\frac{1}{E624-E625} - \frac{1}{E559-E558} \right)$ Device types 01, 03, 05 Device types 02, 04, 06	-12.5 -25	12.5 25	ppm/°C
		450	"	"	"	0000 0000 0000 1111 1111 1110	0000 0000 0000 1111 1111 1110	KA	"	E626 E627	$d_{BPAE} = 19.99 \times 10^6 \times \left(\frac{1}{E627-E626} - \frac{1}{E561-E560} \right)$ Device types 01, 03, 05 Device types 02, 04, 06	-12.5 -25	12.5 25	ppm/°C

TABLE III. Group A Inspection for all device types - Continued.

Subgroup	Symbol	Test no.	Applied voltages ref. pin 9 (figures 8, 10)			Applied digital code-word	DUT digital output code-word	Active relays	Measurement sense lines ref. pin 9		Equations and notes	Limits	
			7 V_{CC} (V)	11 V_{EE} (V)	1 V_{DD} (V)				Pin	Value		Min	Max
5 $T_A = 125^\circ\text{C}$			+15.0	-15.0	+5.0	1111 1111 1110 MSB<----->LSB	1111 1111 1111 MSB<----->LSB	KA	13	V	For end-point linearity error, $L_E(N) = ((E(N+628)+E(N+629))/2 - V(\text{ideal}))/S$ $V(\text{ideal}) = N1 + S \cdot E629 \cdot S/2$ $N1 = \text{Applied ref DAC code-word}$ $S = (E628-E629)/4094$ All device types	-1.0	1.0
	L_{E1}	451	"	"	"	0000 0000 0001	0000 0000 0006	"	"	E628		"	"
	L_{E2}	452	"	"	"	0000 0000 0001	0000 0000 0006	"	"	E629	$L_{E1} = ((E629+E630)/2 - 1 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E3}	453	"	"	"	0000 0000 0010	0000 0000 0016	"	"	E630	$L_{E2} = ((E630+E631)/2 - 2 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E4}	454	"	"	"	0000 0000 0011	0000 0000 0046	"	"	E631	$L_{E3} = ((E632+E633)/2 - 4 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E5}	455	"	"	"	0000 0000 0100	0000 0000 0106	"	"	E632	$L_{E4} = ((E634+E635)/2 - 8 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E6}	456	"	"	"	0000 0000 0111	0000 0000 0446	"	"	E633	$L_{E5} = ((E636+E637)/2 - 16 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E7}	457	"	"	"	0000 0000 1000	0000 0000 1006	"	"	E634	$L_{E6} = ((E638+E639)/2 - 32 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E8}	458	"	"	"	0000 0000 1111	0000 0000 6666	"	"	E635	$L_{E7} = ((E640+E641)/2 - 64 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E9}	459	"	"	"	0000 0001 0000	0000 0001 0006	"	"	E636	$L_{E8} = ((E642+E643)/2 - 128 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E10}	460	"	"	"	0000 0001 0001	0000 0001 0006	"	"	E637	$L_{E9} = ((E644+E645)/2 - 256 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E11}	461	"	"	"	0000 0001 0010	0000 0001 0006	"	"	E638	$L_{E10} = ((E646+E647)/2 - 512 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E12}	462	"	"	"	0000 0001 0011	0000 0001 0006	"	"	E639	$L_{E11} = ((E648+E649)/2 - 768 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E13}	463	"	"	"	0000 0001 0100	0000 0001 0006	"	"	E640	$L_{E12} = ((E650+E651)/2 - 1024 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E14}	464	"	"	"	0000 0001 0101	0000 0001 0006	"	"	E641	$L_{E13} = ((E652+E653)/2 - 1280 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E15}	465	"	"	"	0000 0001 0111	0000 0001 0006	"	"	E642	$L_{E14} = ((E654+E655)/2 - 1536 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E16}	466	"	"	"	0000 0001 1000	0000 0001 0006	"	"	E643	$L_{E15} = ((E656+E657)/2 - 1792 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E17}	467	"	"	"	0000 0001 1001	0000 0001 0006	"	"	E644	$L_{E16} = ((E658+E659)/2 - 2048 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E18}	468	"	"	"	0000 0001 1010	0000 0001 0006	"	"	E645	$L_{E17} = ((E660+E661)/2 - 2304 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E19}	469	"	"	"	0000 0001 1011	0000 0001 0006	"	"	E646	$L_{E18} = ((E662+E663)/2 - 2560 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E20}	470	"	"	"	0000 0001 1100	0000 0001 0006	"	"	E647	$L_{E19} = ((E664+E665)/2 - 2816 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E21}	471	"	"	"	0000 0001 1101	0000 0001 0006	"	"	E648	$L_{E20} = ((E666+E667)/2 - 3072 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E22}	472	"	"	"	0000 0001 1110	0000 0001 0006	"	"	E649	$L_{E21} = ((E668+E669)/2 - 3328 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E23}	473	"	"	"	0000 0001 1111	0000 0001 0006	"	"	E650	$L_{E22} = ((E670+E671)/2 - 3584 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E24}	474	"	"	"	0000 0001 1000	0000 0001 0006	"	"	E651	$L_{E23} = ((E672+E673)/2 - 3840 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E25}	475	"	"	"	0000 0001 1001	0000 0001 0006	"	"	E652	$L_{E24} = ((E674+E675)/2 - 3968 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E26}	476	"	"	"	0000 0001 1010	0000 0001 0006	"	"	E653	$L_{E25} = ((E676+E677)/2 - 4032 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E27}	477	"	"	"	0000 0001 1011	0000 0001 0006	"	"	E654	$L_{E26} = ((E678+E679)/2 - 4064 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E28}	478	"	"	"	0000 0001 1100	0000 0001 0006	"	"	E655	$L_{E27} = ((E680+E681)/2 - 4080 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E29}	479	"	"	"	0000 0001 1101	0000 0001 0006	"	"	E656	$L_{E28} = ((E682+E683)/2 - 4088 \cdot S - E629 \cdot S/2)/S$	"	"
	L_{E30}	480	"	"	"	0000 0001 1110	0000 0001 0006	"	"	E657	$L_{E29} = ((E684+E685)/2 - 4092 \cdot S - E629 \cdot S/2)/S$	"	"
			"	"	"	0000 0001 1111	0000 0001 0006	"	"	E658	$L_{E30} = ((E686+E687)/2 - 4094 \cdot S - E629 \cdot S/2)/S$	"	"

TABLE III. Group A inspection for all device types - Continued.

Subgroup	Symbol	Test no.	Applied voltages ref. pin 9 (figures 8, 10)			Applied digital code-word	DUT digital output code-word	Active relays	Measurement sense lines ref. pin 9			Equations and notes	Limits		Units
			7	11	1	29<----->40 MSB<----->LSB	129<----->16 MSB<----->LSB		Pin	Value	Unit		Min	Max	
5 $T_A = 125^\circ\text{C}$			V_{CC}	V_{EE}	V_{DD}							For differential linearity error, $D_L(N) = (E(N+629) - E(N+628))/S$ $S = (E628-E629)/4094$ All device types			
	D_{LE1}	481	+15.0	-15.0	+5.0	0000 0000 0001	0000 0000 0000	KA	13	V		$D_{LE1} = (E630-E629)/S$	-9	2.0	LSB
	D_{LE2}	482	"	"	"	0000 0000 0010	0000 0000 0010	"	"	"		$D_{LE2} = (E631-E630)/S$	"	"	"
	D_{LE3}	483	"	"	"	0000 0000 0100	0000 0000 0100	"	"	"		$D_{LE3} = (E633-E632)/S$	"	"	"
	D_{LE4}	484	"	"	"	0000 0000 1000	0000 0000 1000	"	"	"		$D_{LE4} = (E635-E634)/S$	"	"	"
	D_{LE5}	485	"	"	"	0000 0001 0000	0000 0001 0000	"	"	"		$D_{LE5} = (E637-E636)/S$	"	"	"
	D_{LE6}	486	"	"	"	0000 0010 0000	0000 0010 0000	"	"	"		$D_{LE6} = (E639-E638)/S$	"	"	"
	D_{LE7}	487	"	"	"	0000 0100 0000	0000 0100 0000	"	"	"		$D_{LE7} = (E641-E640)/S$	"	"	"
	D_{LE8}	488	"	"	"	0000 1000 0000	0000 1000 0000	"	"	"		$D_{LE8} = (E643-E642)/S$	"	"	"
	D_{LE9}	489	"	"	"	0001 0000 0000	0001 0000 0000	"	"	"		$D_{LE9} = (E645-E644)/S$	"	"	"
	D_{LE10}	490	"	"	"	0010 0000 0000	0010 0000 0000	"	"	"		$D_{LE10} = (E647-E646)/S$	"	"	"
	D_{LE11}	491	"	"	"	0011 0000 0000	0011 0000 0000	"	"	"		$D_{LE11} = (E649-E648)/S$	"	"	"
	D_{LE12}	492	"	"	"	0100 0000 0000	0100 0000 0000	"	"	"		$D_{LE12} = (E651-E650)/S$	"	"	"
	D_{LE13}	493	"	"	"	0101 0000 0000	0101 0000 0000	"	"	"		$D_{LE13} = (E653-E652)/S$	"	"	"
	D_{LE14}	494	"	"	"	0110 0000 0000	0110 0000 0000	"	"	"		$D_{LE14} = (E655-E654)/S$	"	"	"
	D_{LE15}	495	"	"	"	0111 0000 0000	0111 0000 0000	"	"	"		$D_{LE15} = (E657-E656)/S$	"	"	"
	D_{LE16}	496	"	"	"	1000 0000 0000	1000 0000 0000	"	"	"		$D_{LE16} = (E659-E658)/S$	"	"	"
	D_{LE17}	497	"	"	"	1001 0000 0000	1001 0000 0000	"	"	"		$D_{LE17} = (E661-E660)/S$	"	"	"
	D_{LE18}	498	"	"	"	1010 0000 0000	1010 0000 0000	"	"	"		$D_{LE18} = (E663-E662)/S$	"	"	"
	D_{LE19}	499	"	"	"	1011 0000 0000	1011 0000 0000	"	"	"		$D_{LE19} = (E665-E664)/S$	"	"	"
	D_{LE20}	500	"	"	"	1100 0000 0000	1100 0000 0000	"	"	"		$D_{LE20} = (E667-E666)/S$	"	"	"
6 $T_A = -55^\circ\text{C}$	M_{CC}	511	"	"	"	$V_{IN(a)} = \text{Max } (-) \text{ through Max } (+)$	0000 0000 0000 1111 1111 1111				$M_{CC} = \text{Number of missing output codes from 0000 0000 0000 to 1111 1111 1111. (Figures 6, 7), all device types}$		0		Codes
	d_{y10}/dI	512	"	"	"	0000 0000 0000	0000 0000 0000		13	E688	V	$d_{y10} = 410^\circ(E556-E688)/dI$	-0.5	0.5	LSB
	d_{y7}/dI	513	"	"	"	0111 1111 1111	0000 0000 0000	KA	"	E689	"	$d_{y7} = 410^\circ(E557-E687)/dI$	-1.0	1.0	"
	d_{yF}/dI	514	"	"	"	0000 0000 0000 1111 1111 1110	0000 0000 0000 1111 1111 1110		"	E690 E691	"	$d_{yF} = 12.49 \times 10^{16} \times \frac{1}{(E559-E587) - \frac{1}{E591-E590}}$	-12.5	12.5	ppm/°C
	d_{yPAE}/dI	515	"	"	"	0000 0000 0000 1111 1111 1110	0000 0000 0000 1111 1111 1110	KA	"	E692 E693	"	$d_{yPAE} = 24.99 \times 10^{16} \times \frac{1}{(E561-E587) - \frac{1}{E593-E592}}$	-12.5	12.5	"

TABLE III. Group A inspection for all device types - Continued.

[illegible]

For Linearity Error, the worst positive and negative error values, as determined by the manufacturer's abbreviated Integral Linearity Error (I_L) test procedure for subgroup 4 shall be within 150 mV. The LSB of the worst positive and negative error values, as determined by the all codes test.

TABLE III. Group A inspection for all device types - Continued.

[illegible]

TABLE III. Group A Inspection for all device types - Continued.

Subgroup	Symbol	Test no.	Applied voltages ref. pin 9 (figures 6, 7)				DUT digital output code-word	Measurement sense lines ref. pin no. 9			Equations and notes	Limits		Units
			7 V_{CC} (V)	11 V_{EE} (V)	1 V_{DD} (V)	13 $V_{IN}(a)$ (V)		Pin	Value	Unit		Min	Max	
$T_A = 25^\circ\text{C}$	t_{DSC}	589	+15.0	-15.0	+5.0	Max (-)	0000 0000 0000	28	t7	ns	$t_{DSC} = t7$	350		ns
	t_{D0}	590 591 592	"	"	"	"	0000 0000 0000	27 22 16	t8 t9 t10	"	Device types 01, 02, 03, 04 Device types 05, 06 Data valid, referenced to CE low to high transition	200 250 "		"
		593 594 595	"	"	"	Max (+)	1111 1111 1111	27 22 16	t11 t12 t13	"	Device types 01, 02, 03, 04 Device types 05, 06 Data valid, referenced to CE low to high transition	200 250 "		"
	t_{HD}	596 597 598	"	"	"	Max (-)	0000 0000 0000	27 22 16	t14 t15 t16	"	All device types Data valid, referenced to CE high to low transition	25 "		"
		599 600 601	"	"	"	Max (+)	1111 1111 1111	27 22 16	t17 t18 t19	"	All device types Data valid, referenced to CE high to low transition	" " "		"
	t_{HS}	602 603 604	"	"	"	Max (-)	0000 0000 0000	27 22 16	t20 t21 t22	"	Device types 01, 02, 03, 04 Device types 05, 06 STS high to low transition referenced to data valid	300 100 "		"
		605 606 607	"	"	"	Max (+)	1111 1111 1111	27 22 16	t23 t24 t25	"	Device types 01, 02, 03, 04 Device types 05, 06 STS high to low transition referenced to data valid	300 100 "		"
	t_{HL}	608 609 610	"	"	"	Max (-)	0000 0000 0000	27 22 16	t26 t27 t28	"	Device types 01, 02 Device types 03, 04, 05, 06 HI-Z delay, referenced to CE high to low transition	100 150 "		"
		611 612 613	"	"	"	Max (+)	1111 1111 1111	27 22 16	t29 t30 t31	"	Device types 01, 02 Device types 03, 04, 05, 06 HI-Z delay, referenced to CE high to low transition	100 150 "		"
	t_{DS}	614	"	"	"	Max (-)	0000 0000 0000	22	t32	"	All device types STS low to high transition, referenced to R/C high to low transition	600 "		"
	t_{DOR}	615 616 617	"	"	"	Max (-)	0000 0000 0000	27 22 16	t33 t34 t35	"	All device types Data valid, referenced to R/C low to high transition	250 "		"
		618 619 620	"	"	"	Max (+)	1111 1111 1111	27 22 16	t36 t37 t38	"	All device types Data valid, referenced to R/C low to high transition	" " "		"

TABLE III. Group A inspection for all device types - Continued.

Subgroup	Symbol	Test no.	Applied voltages ref. pin 9 (figures 6, 7)				DUT digital output code-word	Measurement sense lines ref. pin no. 9			Equations and notes	Limits		Units
			7 V_{CC} (V)	11 V_{EE} (V)	1 V_{DD} (V)	13 $V_{IN(a)}$ (V)		Pin	Value	Unit		Min	Max	
9 $T_A = 25^\circ\text{C}$	t_{HDR}	621	+15.0	-15.0	+5.0	Max (-)	0000 0000 0000	27	t39	ns	All device types Data valid, referenced to R/C high to low transition	25		ns
		622	"	"	"	"	"	22	t40	"		"		"
		623	"	"	"	"	"	16	t41	"		"		"
		624	"	"	"	Max (+)	1111 1111 1111	27	t42	"	All device types	"		"
		625	"	"	"	"	"	22	t43	"	Data valid, referenced to R/C high to low transition	"		"
		626	"	"	"	"	"	16	t44	"		"		"
	R1	627	"	"	"	1/2 VFS	1000 0000 0000	13	1127	mA	All device types	3	7	kohms
		628	"	"	"	Max (+)	1111 1111 1111	27	1128	"	All device types	-40		mA
		629	"	"	"	"	"	22	1129	"	Measured separately to ground	"		"
	I_{OSC}	630	"	"	"	"	"	16	1130	"	(Output = logic "1")	"		"
		631	"	"	"	"	"	28	1131	"		"		"
		632	"	"	"	Max (-)	0000 0000 0000	27	1132	"	All device types	75		"
		633	"	"	"	"	"	22	1133	"	Measured separately to V_{IO6}	"		"
		634	"	"	"	"	"	16	1134	"	(Output = logic "0")	"		"
		635	"	"	"	"	"	28	1135	"		"		"

TABLE III. Group A inspection for all device types - Continued.

Subgroup	Symbol	Test no.	Applied voltages ref. pin 9 (figures 8, 10)				DUT digital output code-word	Measurement sense lines ref. pin 9			Equations and notes	Limits		Units
			7 V_{CC} (V)	11 V_{EE} (V)	1 V_{DD} (V)	129 $V_{IN(a)}$ (V)		Pin	Value	Unit		Min	Max	
9 $T_A = 25^\circ\text{C}$	INT	636	+15.0	-15.0	+5.0	0111 1111 1111	0000 0000 0000	13	E772	V	Range = 16% to 84% All device types	-0.5	0.5	LSB
		637	"	"	"	1111 1111 1110	1111 1111 1110	13	E773	V		-0.5	0.5	LSB

4.4 Quality conformance inspection. Quality conformance inspection shall be in accordance with MIL-M-38510 and as specified herein. Inspections to be performed shall be those specified in method 5005 of MIL-STD-883, and herein for groups A, B, C, and D inspections (see 4.4.1 through 4.4.4).

4.4.1 Group A inspection. Group A inspection shall be in accordance with table I of method 5005 of MIL-STD-883, and as follows:

- a. Tests shall be as specified in table II herein.
- b. Subgroups 10 and 11 shall be omitted.
- c. Subgroup 8 (LE (All codes test) $-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$, class B only) shall be performed only for initial qualification and after process or design changes which may affect the Integral Linearity error. The LTPD for subgroup 8 shall be 5.

4.4.2 Group B inspection. Group B inspection shall be in accordance with table II of method 5005 of MIL-STD-883 and as follows:

- a. Electrical parameters shall be as specified in table II herein. For class S devices, delta limits shall apply only to subgroup 5 of group B inspection.
- b. Steady-state life test for class S devices shall be in accordance with table IIa of method 5005 of MIL-STD-883, using the circuit shown on figure 5. If the alternate burn-in conditions are used the circuit shown on figure 5 shall be used.

4.4.3 Group C inspection. Group C inspection shall be in accordance with table III of method 5005 of MIL-STD-883 and as follows:

- a. End-point electrical parameters shall be as specified in table II herein. Delta limits shall apply only to subgroup 1 of group C inspection for class B devices.
- b. Steady-state life test (method 5005 of MIL-STD-883) conditions:
 - (1) Test condition B, using the circuit shown on figure 5; or test condition D, using the circuit shown on figure 5.
 - (2) $T_A = +125^{\circ}\text{C}$ minimum.
 - (3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-STD-38510 and method 1005 of MIL-STD-883.

4.4.4 Group D inspection. Group D inspection shall be in accordance with table IV of method 5005 of MIL-STD-883 and as follows:

- a. End-point electrical parameters shall be as specified in table II herein.
- b. This group shall be measured only for initial qualification and thereafter for group D tests at $+25^{\circ}\text{C}$.

TABLE IV. Group C end-point electrical parameters.

Table III test no.	Device type	Symbol	Delta ^{1/}		End-point limits		
			Min	Max	Min	Max	Units
382	01,02	V_{IO}	-0.5	0.5	-1.0	2.0	LSB
	03,04,05,06	V_{IO}	-0.5	0.5	-2.0	3.0	LSB
383	A11	B_Z	-1.0	1.0	-5.5	4.5	LSB
384	01	A_E	-0.1	0.1	-0.225	0.225	%FSR
	02	A_E	-0.1	0.1	-0.35	0.35	%FSR
	03,04,05,06	A_E	-0.1	0.1	-0.4	0.4	%FSR

^{1/} Delta limits apply to the measured value (see delta limit definition in MIL-M-38510).

4.5 Methods of inspection. Methods of inspection shall be as specified in the appropriate tables. Electrical test circuits as prescribed herein or in the referenced test methods of MIL-STD-883 shall be acceptable. Other test circuits shall require the approval of the qualifying activity.

4.5.1 Voltage and current. All voltages given are referenced to the microcircuit ground terminal. Currents given are conventional and positive when flowing into the reference terminal.

4.5.2 Life test and burn-in cooldown procedure. When devices are measured at 25°C following application of steady-state life or burn-in test condition, they shall be cooled to within 10°C of their power stable condition at room temperature prior to the removal of the bias.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

6.1 Intended use. Microcircuits conforming to this specification are intended for original equipment design applications and logistic support of existing equipment.

6.2 Ordering data. The acquisition document should specify the following:

- a. Complete part number (see 1.2).
- b. Requirements for delivery of one copy of the quality conformance inspection data pertinent to the device inspection lot to be supplied with each shipment by the device manufacturer, if applicable.
- c. Requirements for certificate of compliance, if applicable.
- d. Requirements for notification of change of product or process to the contracting activity in addition to notification to the qualifying activity, if applicable.
- e. Requirements for failure analysis (including required test condition of method 5003 of MIL-STD-883), corrective action, and reporting of results, if applicable.
- f. Requirements for product assurance options.
- g. Requirements for special lead lengths or lead forming, if applicable. These requirements shall not affect the part number.
- h. Requirements for "JAN" marking.

6.3 Abbreviations, symbols, and definitions. Unless otherwise defined abbreviations, symbols, and definitions used herein are defined in MIL-M-38510, MIL-STD-1331, and as follows:

AE	- - - - -	Gain error
AO	- - - - -	12 or 8 bit conversion initiation control
BZ	- - - - -	Bipolar zero input voltage for mid-code output transition
CE	- - - - -	Chip enable
CS	- - - - -	Chip select, not
dAE/dT	- - - - -	Gain error drift with respect to temperature
dBZ/dT	- - - - -	Bipolar zero drift
DLE	- - - - -	Differential linearity error
dVIO/dT	- - - - -	Unipolar input offset voltage drift
ICC, IEE, ILOGIC	- - - - -	Input currents for positive (+15 V), negative (-15) and logic (+5 V) voltage supplies, respectively
IIL	- - - - -	Digital low level input current
IIH	- - - - -	Digital high level input current
IOSC	- - - - -	Output short circuit current
IZH	- - - - -	Digital output impedance (output forced high)

IZL - - - - -	Digital output impedance (output forced low)
HI-Z - - - - -	High impedance output mode
LE - - - - -	Integral linearity error
LSB - - - - -	Least significant bit
m(N) - - - - -	Mode designation for output operation
Max (+) - - - - -	The positive voltage required at the analog voltage input pin to produce a digital code of 1111 1111 1111 at the DUT output pins.
Max (-) - - - - -	The negative voltage required at the analog voltage input pin to produce a digital code of 0000 0000 0000 at the DUT output pins.
MCC - - - - -	Missing code check
MSB - - - - -	Most significant bit
NT - - - - -	Transition uncertainty due to all sources (ie noise, settling time, etc.)
Pd - - - - -	Power dissipation
PSS - - - - -	Power supply sensitivity
R/C - - - - -	Read and convert, not
Ri - - - - -	Input resistance of the analog input
STS - - - - -	Status
TA - - - - -	Ambient temperature
t _c - - - - -	Conversion time
t _{dd} - - - - -	Data access time from CE high
t _{DDR} - - - - -	Data access time from R/C high
t _{DS} - - - - -	Status delay high from R/C low
t _{DSC} - - - - -	Status delay high from CE high
t _{HD} - - - - -	Data valid delay from CE low
t _{HDR} - - - - -	Three-state output delay from R/C low
t _{HL} - - - - -	Three-state output delay from CE low
t _{HS} - - - - -	Status delay low from data valid
VFSR - - - - -	Full scale voltage range
VIN(a) - - - - -	Analog input voltage
VO - - - - -	Digital output voltage
VOH - - - - -	Digital high level output voltage
VOL - - - - -	Digital low level output voltage
VREF - - - - -	Reference output voltage
12/8 - - - - -	12 or 8 bit parallel output enable control

Bipolar mode. Bipolar mode is the D/A converter operation mode that provides both positive and negative output voltages in response to an offset binary input code.

Integral linearity error. Integral linearity error is the difference between the average of two input analog voltages, required to establish adjacent output code-word transitions, with respect to the ideal voltage at the same bit mid-point as defined by a straight line that passes through points extrapolated one half LSB from the first and the last bit transitions.

Differential linearity. Differential linearity is the difference between two input analog voltages required to establish adjacent output code-word transitions. The ideal differential linearity is 1 LSB.

Differential linearity error. Differential linearity error is the difference between the actual and the ideal differential linearity values for any two adjacent code-word transitions.

Full-scale range. Full-scale range is the voltage difference between the input voltages at the first bit transition and the last bit transition plus twice the voltage difference between two adjacent bit transitions.

Least significant bit. The last significant bit is the bit in the output code that carries the least weight. The value of the least significant bit is the average difference between the analog input voltages at two adjacent output bit transitions. The ideal difference voltage is the value of the full scale range divided by 1024.

Monotonicity. A device is monotonic if the ratio of the incremental change in output to incremental change in input does not change polarity over the full scale range.

Most significant bit. The most significant bit is the bit in the output code that carries the most weight. It is the output bit that changes state when the analog input voltage change from its most positive value to one-half of the full scale range.

6.4 Logistic support. Lead materials and finishes (see 3.3) are interchangeable. Unless otherwise specified, microcircuits acquired for Government logistic support will be required to device class B (see 1.2.2), lead material and finish C (see 3.3). Longer length leads and lead forming shall not affect the part number.

6.5 Substitutability. The cross-reference information below is presented for the convenience of users. Microcircuits covered by this specification will functionally replace the listed generic-industry type. Generic-industry microcircuit types may not have equivalent operational performance characteristics across military temperature ranges or reliability factors equivalent to MIL-M-38510 device types and may have slight physical variations in relation to case size. The presence of this information shall not be deemed as permitting substitution of generic-industry types for MIL-M-38510 types or as a waiver of any of the provisions of MIL-M-38510.

<u>Military device type</u>	<u>Generic-Industry device type</u>
01	574AU (monolithic)
02	574AT (monolithic)
03	574AU (hybrid)
04	574AT (hybrid)
05	674AU (monolithic)
06	674AT (monolithic)

6.6 Handling. MOS devices must be handled with certain precautions to avoid damage due to accumulation of static charge. Input protective devices have been designed in the chip to minimize the effect of this static buildup. However, the following handling practices are recommended:

- a. Devices should be handled on benches with conductive and grounded surface.
- b. Ground test equipment, tools and operator.
- c. Do not handle devices by the leads.
- d. Store devices in conductive foam or carriers.
- e. Avoid use of plastic, rubber, or silk in MOS areas.
- f. Maintain relative humidity above 50 percent, if practical.
- g. Unused logic inputs should be connected to logic high or logic low but not left open.
- h. Disconnect all low impedance equipment and input signals from the device before switching off dc power supplies.
- i. Switch off power supplies before inserting or removing devices from circuits.

Custodians:

Army - ER
Navy - EC
Air Force - 17

Review activities:

Army - AR, MI
Navy - OS, SH, TD
Air Force - 11, 19, 85, 99
DLA - ES

User activities:

Army - SM
Navy - AS, CG, MC

Civil agency coordinating activity:

NASA - NA

Preparing activity:

Air Force - 17

Agent:

DLA - ES

(Project 5962-0787)